3 Axis Vibration Sensor: M-A342VD1

Features

- Capable of measuring velocity, velocity RMS, and velocity Peak to Peak (ISO10816/20816 compliant)
- Flat Frequency Response : 10 Hz ~ 1000 Hz (-3 dB)
- Insensitive to magnetic influences
- Wide output range : ±100 mm/s (110 dB)
- Low Noise : $1.4 \times 10^{-4} \text{ (mm/s)}/\sqrt{\text{Hz Typ.}}$
- 3-Axis Digital Output : SPI/UART
- Capable of measuring Displacement : 1 Hz ~ 100 Hz
- Low cross-axis sensitivity (capable of 0.1% with alignment compensation by host post-process) and low sensitivity error (1550×10⁻⁶) to ensure high accuracy
- Built-in Self Test Function

Application

- Condition Based Maintenance (CBM)
- Machine Health Monitoring (MHM)
- Structural Health Monitoring (SHM)
- Vibration Analysis, Control and Stabilization
- Motion Analysis and Control
- Lissajous Analysis

Typical Performance Characteristic

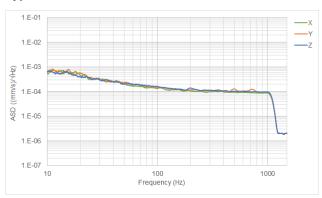


Figure Noise Density (Velocity Output)

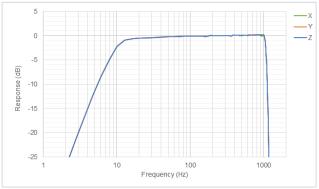


Figure Frequency Response (Velocity Output)

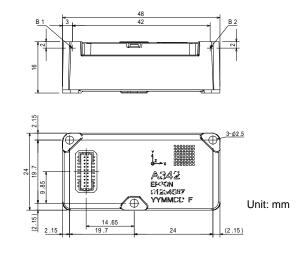


Description

The M-A342 is a three axis digital velocity/displacement output vibration sensor featuring low noise, high stability, and low power consumption using fine processing technology of Quartz.

Incorporating high accuracy, wide bandwidth, and durability, the versatile M-A342 is well suited to a widerange of challenging applications such as Condition Based Maintenance (CBM), Machine Health Monitoring (MHM), and Structural Health Monitoring (SHM).

Outline Dimentions



Block Diagram

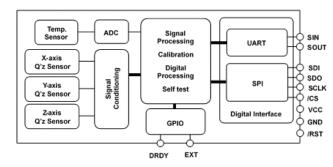


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Revision History

Rev. No.	Date	Page	Description		
20220210	2022/2/10	ALL	New release.		
20220401	2022/4/1	8	Product Number Change		

Ordering Information

The product can be ordered with the following numbers. Please inquire separately about details.

Product Model Number	Product Name	Comments
X2F000021000100	M-A342VD1	This product.

Evaluation tools

Evaluation tools can be provided for this product. Please inquire separately about details.

Product Model Number	Product Name	Comments
X2H000021000200 M-G32EV041 L		USB Evaluation Board for Accelerometer/IMU.
		Option to connect M-A342 to the USB port of a PC.
X2H000021000300 M-G32EV051 I		Relay Board for Accelerometer/IMU.
		Option to reduce the vibration effect of the USB cable.
-	Vibration Logger	Accelerometer/Vibration sensor Logger Software.
		For more information, please contact us.

Symbols



• Compliant with the EU RoHS directive.

* About products without the Pb-Free label

Product terminals are lead-free but the internal components of the product contain lead (high melting point solder lead as well as the lead contained in the glass of an electronic component are both not applicable under the EU RoHS directive).

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1. Specifications

1.1. Absolute Maximum Ratings

Table 1.1 Absolute Maximum Rating

Parameter	Min.	Тур.	Max.	Unit
V _{CC} to GND	-0.3		3.6	V
Digital Input Voltage to GND	-0.3		Vcc + 0.3	V
Digital Output Voltage to GND	-0.3		V _{CC} + 0.3	V
Storage Temperature Range	-40		85	°C
Acceleration (Half-sine 0.2 ms)			1000	G

Precautions on excitation of structural resonance

If the structural resonance frequency of this product around 4.5 kHz is excited, the input signal may be improperly amplified, and proper measurement may not be performed. Confirm that there is no influence from the resonance frequency by performing a structural resonance level test (see 4.7 Self-Test) when using this product.

Precautions concerning ESD

- · Electrostatic discharge (ESD) may damage this product.
- · Please take appropriate measures against electrostatic discharge (ESD) when storing and handling this product.
- Damage by electrostatic discharge (ESD) can cause very small performance deterioration, partial malfunction, or complete breakdown.
- This is a high precision product and may not conform to specification even with very small performance degradation due to improper usage or handling.

1.2. Recommended Operating Condition

Table 1.2 Recommended Operating Condition

Parameter	Condition	Min.	Тур.	Max.	Unit
Vcc to GND		3.15	3.3	3.45	V
Digital Input Voltage to GND		GND		Vcc	V
Digital Output Voltage to GND		-0.3		V _{CC} + 0.3	V
Operating Temperature Range		-30		85	ů
Start up Time	Power-on to start output.			900	ms

1.3. Performance and Electrical Specifications

Table 1.3 Sensor Specifications

 T_a = -30 °C ~ +85 °C, Vcc = 3.15 V ~ 3.45 V, \leq ±1 G, unless otherwise noted.

1a 00 0 100 0, 100 =	1 0.10 V 0.10 V, = ±1 O, unloco otherwice		1		1
Parameter	Test Conditions / Comments	Min.	Тур.	Max.	Unit
VELOCITY					
Sensitivity					
Output Range	f = 10 Hz ~ 1000 Hz	-100		+100	mm/s
Scale Factor	2 ⁻²² (m/s)/LSB		2.38 x 10 ⁻⁴		(mm/s)/LSB
Sensitivity Error	+25 °C, ≤ 1 G	-1550		+1550	x10 ⁻⁶ of FS
Nonlinearity	≤ 1 G, Best fit straight line, +25 °C	-0.15		+0.15	% of FS
Cross Axis Sensitivity	No alignment correction		±0.9 *3		%
Noise					
Noise Density	+25 °C, Average, f = 200 Hz ~ 1000 Hz		1.4 x 10 ⁻⁴		(mm/s)/√Hz, rms
Cantilever Resonance Frequency	+25 °C, V _{CC} = 3.3 V		4460		Hz
Frequency Property					
Frequency Range	-3 dB at +25 °C		10 ~ 1000		Hz
DISPLACEMENT					
Sensitivity					
Output Range	f = 1 Hz ~ 100 Hz	-200		+200	mm
Scale Factor	2 ⁻²² m/LSB		2.38 x 10 ⁻⁴		mm/LSB
Nonlinearity	≤ 1 G, Best fit straight line, +25 °C	-0.15		+0.15	% of FS
Cross Axis Sensitivity			±0.9 *3		%
Noise					
Noise Density	+25 °C, Average, f = 20 Hz ~ 100 Hz		0.7 x 10 ⁻⁵		mm/√Hz, rms
Frequency Property					
Frequency Range	-3 dB at +25 °C		1 ~ 100		Hz
TEMPERATURE SENSOR					
Output Range		-40		+85	°C
16-bit Scale Factor *1	Output = 2634 (0x0A4A) at +25 °C		-0.0037918		°C/LSB
8-bit Scale Factor *1	Output = 2634 (0x0A4A) at +25 °C		-0.9707008		°C/LSB
RELIABILITY					
MTBF*2	JIS-C5003 T _a = +25 °C	87600			h

^{*1)} This is a reference value used for the internal temperature correction, and is not guaranteed to accurately output the interior temperature.

^{*2)} The MTBF is an estimated value derived from the result of high temperature operation with a system requirement of T_a = 25 °C and a 60 % reliability level.

^{*3)} When the alignment is corrected by the host, the cross axis sensitivity that can be achieved is Typ. 0.1 %. See 4.15 Alignment Compensation.

Note) The values in the specifications are based on the data calibrated at the factory. The values may change according to the way the product is used.

Note) The Max/Min value is the maximum/minimum value of the design or factory shipment examination, unless otherwise specified.

Note) The calibrated standard 1G gravitational acceleration value is 9.80665 m/s².

Table 1.4 Interface Specifications

 $T_a = 25$ °C, $V_{CC} = 3.3$ V, unless otherwise noted.

Parameter	Test Conditions	Min.	Тур.	Max.	Unit
LOGIC INPUTS*1					
Positive Trigger Voltage	Schmitt	1.37		2.29	V
Negative Trigger Voltage	Schmitt	0.69		1.24	V
Hysteresis Voltage	Schmitt	0.53			V
Input Current	$VI = V_{CC}$ or GND		0.5		μΑ
Input Capacitance			2.5		pF
Sleep Wake-up Input Width		1			μs
RST Low Pulse Width		100			ms
Pull-up resistor			220		kΩ
DIGITAL OUTPUTS*1					
Output High Voltage	ISOURCE = 20 µA	Vcc - 0.1			V
Output Low Voltage	ISINK = 20 µA			0.1	V
FUNCTIONAL TIMES*2	Time until data is available				
Power-On Start-Up Time*3				900	ms
Reset Recovery Time*3				970	ms
Flash Backup Time				310	ms
Flash Reset Time				2300	ms
	ACC Test , TEMP Test , VDD Test			300	ms
Self Test Time	Structural Resonance Level Test			820	ms
	Flash Test			5	ms
Output Mode Setting Time				118	ms
Sampling Start Time	Configuration mode to Sampling mode			5	ms
Sampling Stop Time	Sampling mode to Configuration mode			1	ms
Sleep Wake-up Time				16	ms
	Velocity Raw data		3000		Sps
Output Data Data	Displacement Raw data		300		Sps
Output Data Rate	Velocity RMS/PP data	0.1		25.5	S
	Displacement RMS/PP data	1		255	s
Clock Accuracy				±0.001	%
	Velocity output, Average		29	32	mA
Power Supply Current	Displacement output, Average		21.5	24	mA
	Sleep mode		1.3	2.0	mA

^{*1)} Digital I/O signal pins operate at 3.3V inside the unit.

Note) These parameters are not included in the factory test items but these characteristics are confirmed.

^{*2)} These specifications do not include the effect of temperature fluctuation and response time of the internal filter.

^{*3)} Do not access the interface during startup and reinitialization.

1.4. Timing Specifications

Table 1.5 SPI Timing Specifications

 T_a = 25 °C, V_{CC} = 3.3 V, unless otherwise noted.

Parameter	Description	Min.	Тур.	Max.	Unit
NORMAL MODE			-		
fSCLK		0.01		2.0	MHz
tSTALL	Stall period between data	20			μs
tWRITERATE	Write rate	40			μs
tREADRATE	Read rate	28			μs
BURST MODE					
fSCLK		0.01		2.0	MHz
tSTALL1	Stall period between data	45			μs
tSTALL2	Stall period between data	0			μs
tREADRATE2	Read rate	8			μs
COMMON					
tCS	Chip select to clock edge	10			ns
tDAV	SO valid after SCLK edge			80	ns
tDSU	SI setup time before SCLK rising edge	10			ns
tDHD	SI hold time after SCLK rising edge	10			ns
tSCLKR, tSCLKF	SCLK rise/fall times			20	ns
tDF, tDR	SO rise/fall times			20	ns
tSFS	high after SCLK edge CS	80			ns

Note) These parameters are not included in the factory test items but these characteristics are confirmed.

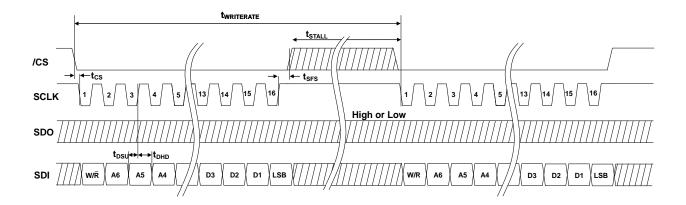


Figure 1.1 SPI Write Timing and Sequence

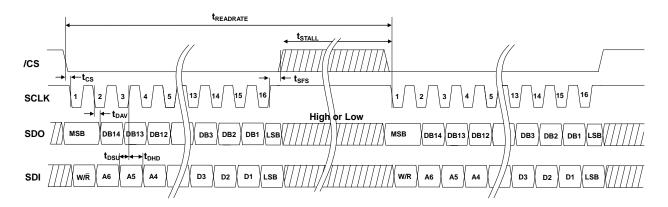


Figure 1.2 SPI Read Timing and Sequence

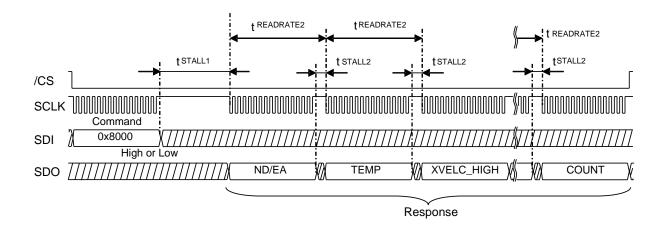


Figure 1.3 SPI Read Timing and Sequence (BURST MODE)

1.5. Socket Pin Layout and Functions

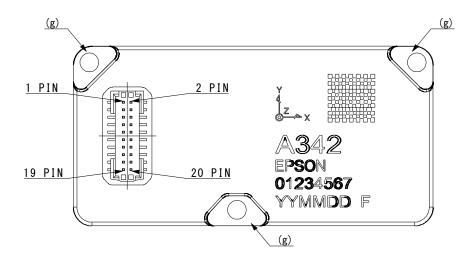


Figure 1.4 Socket Pin Assignment

Precautions (Important)

- Frame Ground (g) must be connected to one of the GND pins (3, 4, 8, or 15).
- Do not insert or remove the socket while the power is on. Otherwise, overvoltage or overcurrent may be applied to the socket pins, which may damage the circuitry inside the product.
- Do not force the connector into the socket when the socket pins are not in the proper position. Otherwise, the socket guide may be damaged or the pins may be bent.

Pin No.	Mnemonic	Type*1	Description
1	SCLK	I	SPI Serial Clock *2
2	SDO	0	SPI Data Output *2
5	SDI	I	SPI Data Input *2
6	/CS	I	SPI Chip Select *2
7	SOUT	0	UART Data Output *2
9	SIN	I	UART Data Input *2
13	DRDY	0	Data Ready *3
14	EXT	I	Sleep Wakeup Input *6
16	/RST	I	Reset *4
10, 11, 12	VCC	S	Power Supply 3.3V
3, 4, 8, 15	GND	S	Ground *5
17, 18, 19, 20	NC	N/A	Do Not Connect

Table 1.6 Pin Function Descriptions

Note) All input pins have weak pull up resistors inside this product.

^{*1)} Pin Type I: Input, O: Output, I/O: Input/Output, S: Supply, N/A: Not Applicable

^{*2)} Please connect either SPI or UART. Connecting both SPI and UART at the same time may cause malfunction. Please connect unused input pins to V_{CC} via a resistor.

^{*3)} Please refer to **DRDY_ON** of register: MSC_CTRL [0x02 (W1)], bit [2] for pin function selection.

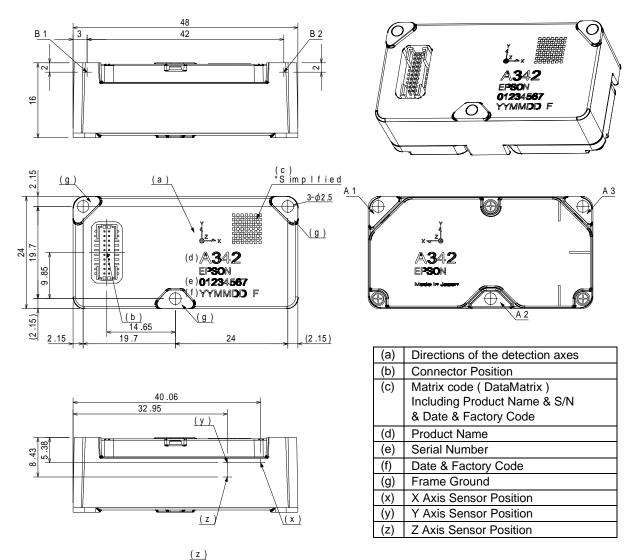
^{*4)} When /RST pin is not used, fix it to High (Vcc) level via a resistor.

^{*5)} Please connect Frame Ground (g) to any GND pin (No.3, 4, 8, 15).

^{*6)} Please refer to EXT_POL of register: MSC_CTRL [0x02 (W1)], bit [5] for pin polarity.

2. Mechanical Dimensions

2.1. Outline Dimensions



2 .95 40 .06

Table 2.1 Header Part Number

Maker	Parts Number	RoHS Compliant
Samtec	FTMH-110-02-H-DV-ES	Yes

The recommended sockets to be used on the host side are shown in Table 2.2.

Table 2.2 Socket Part Number

Maker	Parts Number	RoHS Compliant
Samtec	CLM-110-02-H-D	Yes
Samtec	CLM-110-02-L-D	Yes

Figure 2.1 Outline Dimensions (millimeters)

- *1) This product is calibrated based on the surfaces A1, A2, A3, and B1, B2.
- *2) In order to demonstrate the performance of the product properly, please fix surfaces A1, A2, A3 to rugged parts with M2 screw.
- *3) When high connection reliability is required, please tighten this product together with the board on which the connector is mounted.

3. Typical Performance Characteristics

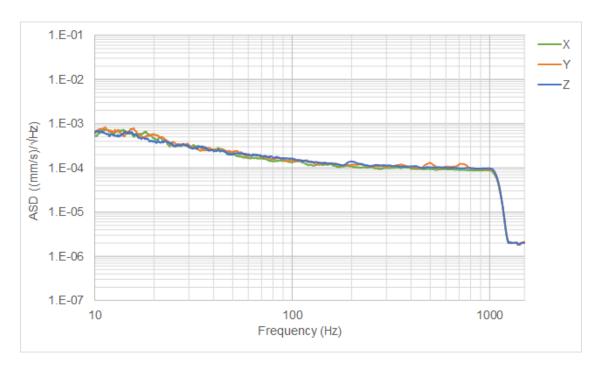


Figure 3.1 Noise Frequency Characteristic (Velocity Output)

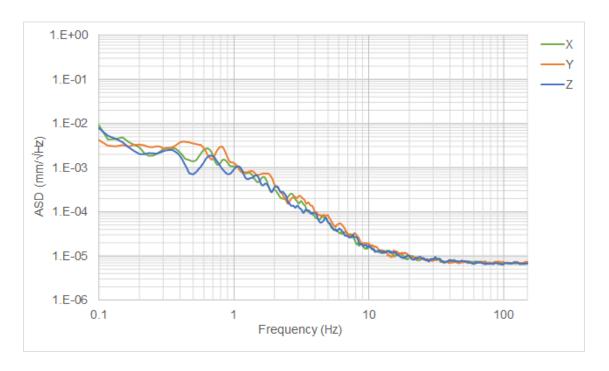


Figure 3.2 Noise Frequency Characteristic (Displacement Output)

^{*1)} The above graph is a typical example of the product characteristics, and is not guaranteed by the specification.

^{*2)} ASD: Amplitude Spectral Density

4. Basic Operation

4.1. Connection To Host

The device supports two types of serial interface: UART and SPI. Only one interface type should be selected and used at any given time (not both). Connecting both SPI and UART at the same time may result in malfunction of the device. The example wiring connection is provided below as a reference.

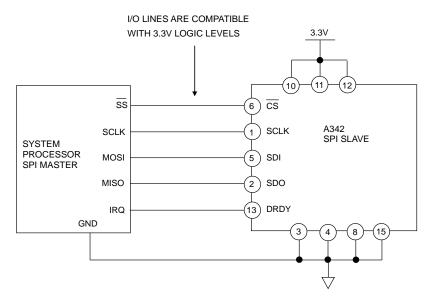


Figure 4.1 SPI Connection

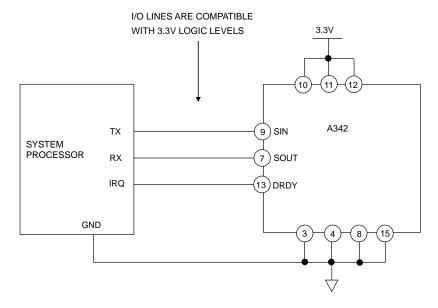


Figure 4.2 UART Connection

4.2. Operation Mode

The following three operational modes are available in the device. Only when UART is used, Sampling mode has two submodes: Manual mode and Auto mode.

- (1) Configuration mode
- (2) Sampling mode
 - Manual mode
 - Auto mode (for UART only)
- (3) Sleep mode

Immediately after a hardware reset or power-on, internal initialization starts. During the internal initialization, all the register values and states of external pins are undefined. After the internal initialization is completed, the device goes into Configuration mode automatically, except when using the UART interface when AUTO_START and UART_AUTO sampling are both enabled (the device then goes into Sampling mode automatically). To change the operation mode, write to MODE_CMD (MODE_CTRL [0x02(W0)], bit [9:8]) (*1) and make various changes to the sensor setting in Configuration mode (*2). After configuration is completed, go to Sampling mode to read out the temperature and velocity/displacement data. When shifting to the sleep mode, the internal circuit operation stops and the current consumption during standby can be reduced. The return time from sleep mode can be shorter than the initialization time from startup. The device can wake up from sleep mode by detecting an edge trigger on the EXT pin.

By executing software reset (Register: GLOB_CMD [0x0A (W1)], write 1 to **SOFT_RST** in bit [7]), internal initialization operation is executed regardless of the current operation mode.

When the UART interface is used, writing to **UART_AUTO** (UART_CTRL [0x08(W1)], bit [0]) can switch between Manual sampling and Auto sampling (*3). When SPI interface is used, Manual sampling must be selected. Otherwise, the device does not work properly.

*1) The following explains register notation used in this document.

For example, MODE_CTRL [0x02(W0)], bit [9:8] refers to:

- MODE_CTRL: Register Name
- [0x02(W0)]: First number is the Register Address, (W0) refers to Window Number "0"
- bit [9:8]: Bits from 9 to 8
- *2) Make sure that the device is in Configuration mode when you write to the registers to configure operational settings. In Sampling mode, writing to registers is ignored except the following cases.
 - Writing to MODE_CMD (MODE_CTRL [0x02(W0)], bit [9:8])
 - Writing to SOFT_RST (GLOB_CMD [0x0A(W1)], bit [7])
 - Writing to WINDOW_ID (WIN_CTRL [0x7E(W0/W1)], bit [7:0])
- *3) While the device is with UART Auto sampling and sensor sampling is active, register read access is not supported.

 Otherwise, the sampling data transmitted with the UART Auto sampling will be corrupted by the response data from the register read.

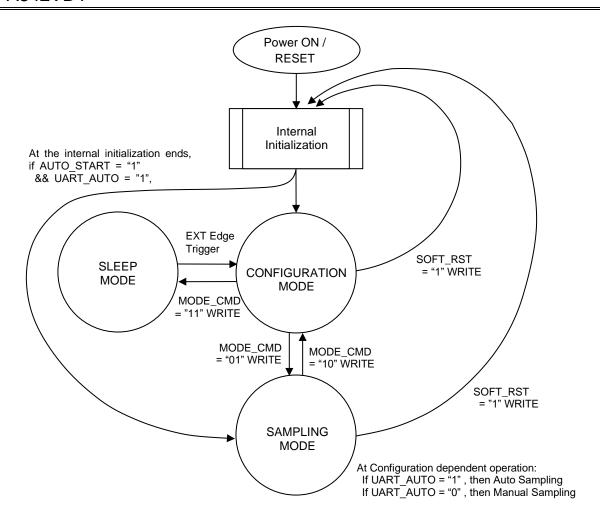


Figure 4.3 Operational State Diagram

4.3. Functional Block

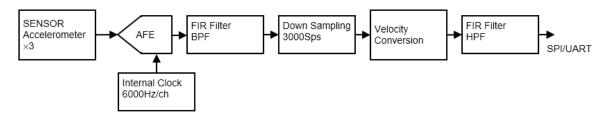


Figure 4.4 Functional Block Diagram - Velocity

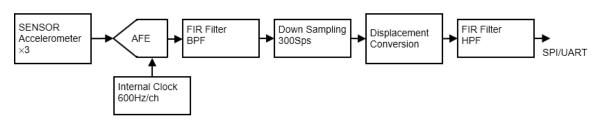


Figure 4.5 Functional Block Diagram - Displacement

4.4. Data Output Timing

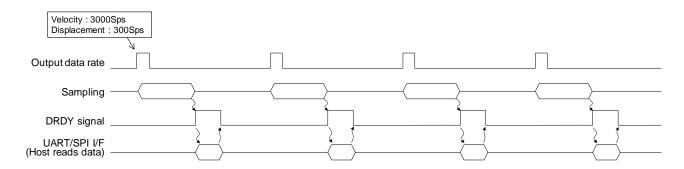


Figure 4.6 Data Output Timing

4.5. Data Ready Signal

The Data Ready Signal is asserted when one sampling cycle completes and registers are updated with new sensor values. When the sensor values are read out, the Data Ready signal becomes negated as shown in Figure 4.6. With UART AUTO sampling enabled, the Data Ready signal becomes negated just before data is output.

The Data Ready Signal is output to the DRDY pin when the **DRDY_ON** (MSC_CTRL [0x02(W1)], bit [2]) is set to "1". The polarity of the signal can be changed by the **DRDY_POL** of MSC_CTRL [0x02(W1)], bit [1] register.

The Data Ready Signal is the logical sum of all the ND flags corresponding to each sensor value. If all the ND flags are disabled in the **ND_EN** (SIG_CTRL [0x00(W1)], bit [15,11:9]), the Data Ready will not be asserted. On the other hand, if all the sensor values enabled in the **ND_EN** (SIG_CTRL [0x00(W1)], bit [15,11:9]) are not read out, the Data Ready signal is kept asserted and never becomes negated.

4.6. Sampling Counter

1) 16-bit Counter

By reading COUNT [0x0A(W0)] register, the counter value, which is incremented based on the sampling completion timing of the internal Analog Front End, can be read. The count interval timing is based on the precision of the internal reference oscillator (crystal):

For velocity: 1/6000 Sps ≒ 167 μs/count
 For displacement: 1/600 Sps ≒ 1.67 ms/count

Additionally, during UART/SPI burst mode or with UART Auto sampling, the counter value can be included in the response format by setting the **COUNT_OUT** (BURST_CTRL [0x0C(W1)], bit [1]). For information about the response format, see 5.3 Data Packet Format.

2) 2-bit Counter

By reading **2BIT_COUNT** of register: TEMP2 [0x2E(W0)], bit [1:0], a 2-bit count value that counts up at each output rate can be obtained. Also, the 2-bit count value can be included in the burst output by setting the TEMP_SEL of the register in SIG_CTRL [0x00(W1)], bit [1] to temperature format 2 and enabling the temperature output by the register setting in BURST_CTRL [0x0C(W1)], bit [14].

4.7. Self Test

This product has the following self test functions. For information about the execution time of the self test, see "Self Test Time" in Table 1.4 Interface Specifications.

Acceleration Value

In this sensor, velocity / displacement outputs are provided based on the acceleration values. When there is no obvious abnormality, the acceleration values for X, Y, and Z axes should be within -32 m/s 2 ~ 32 m/s 2 . Additionally, the net

magnitude of the acceleration vector of X, Y, and Z axes acceleration values should be within 0 m/s 2 ~ 32 m/s 2 (these ranges appear to be wide because zero point calibration is not performed in this sensor for acceleration values).

When performing the self test, make sure the device does not move during the test and the test is conducted in a place without vibration.

To use this function, execute **ACC_TEST** of register: MSC_CTRL [0x02(W1)], bit [10], check the **ACC_ERR_ALL** of register DIAG_STAT1 [0x04(W0)], bit [1] for diagnostic result. The magunitude value of the 3-dimensional acceleration vector can be obtained by reading **ACC_VEC** of register: ACC_SELFTEST_DATA1 [0x2A(W0)], bit [7:0].

Sensitivity

By utilizing the above **ACC_VEC** of register: ACC_SELFTEST_DATA1 [0x2A(W0)], bit [7:0] and the gravitational acceleration under the measurement environment, the validity of the sensitivity can be evaluated. Follow the procedure below with reference to Figure 4.7.

- ① Place the sensor on a horizontal surface with the target axis parallel to the gravity direction.
- ② Execut **ACC_TEST** of the register: MSC_CTRL [0x02(W1)], bit [10], read the acceleration value of the target axis from the register ACC_SELFTEST_DATA1 [0x2A(W0)] or the register: ACC_SELFTEST_DATA2 [0x2C(W0)].
- 3 Rotate the target axis 90 degrees to the horizontal plane, and perform 2 again.
- 4 Confirm that there is no obvious abnormality if the difference between the acceleration values in 2 and 3 is within $7.75 \text{ m/s}^2 \sim 11.75 \text{ m/s}^2$.

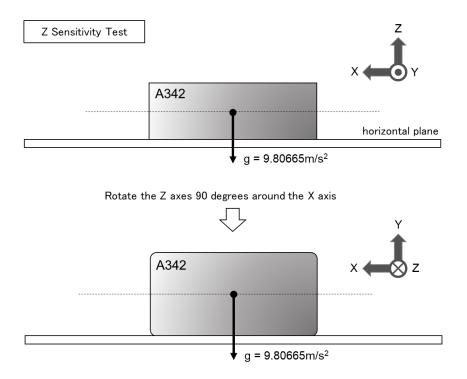


Figure 4.7 Example of the Sensor Placement for Sensitivity Test

Temperature Value

Determine whether the temperature sensor is operating properly.

To use this function, execute **TEMP_TEST** of register: MSC_CTRL [0x02 (W1)], bit [9], check the **TEMP_ERR** of register: DIAG_STAT1 [0x04 (W0)], bit [9] for diagnostic result.

Power Supply Voltage Level

Determine whether the power supply voltage is within 3.0V to 3.6V.

To use this function, execute **VDD_TEST** of register: MSC_CTRL [0x02(W1)], bit [8], check the **VDD_ERR** of register: DIAG_STAT1 [0x04(W0)], bit[8] for diagnostic result.

Nonvolatile memory

Determine whether the Nonvolatile memory is operating properly by consistency test of data in nonvolatile memory.

To use this function, execute **FLASH_TEST** of register: MSC_CTRL [0x02(W1)], bit [11], check the **FLASH_ERR** of register: DIAG_STAT1 [0x04(W0)], bit [2] for diagnostic result.

Structural Resonance Level

Determine whether the input signal level amplified by the structural resonance is within the expected range. For the determination details, refer to Table 6.2 in "6.6 DIAG_STAT2 Register (Window 0)".

Prior to the permanent installation of the sensor, the structural resonance level can be identified, which provides information for considering how to mount the sensor or where to place the sensor during the installation procedure.

To use this function, execute **EXI_TEST** of register: MSC_CTRL [0x02(W1)], bit [15], check the **EXI_LEVEL** of register: DIAG_STAT2 [0x0C(W0)], bit [13:8] for diagnostic result.

4.8. Threshold Detection

When the sensor value exceeds the preset threshold, an alarm is displayed. The threshold value register is common for all output physical quantities, so make sure to set the threshold value according to the output physical quantity. The factory default setting of the threshold is the upper limit of the velocity output.

The alarm threshold is set in the registers: XA_ALARM [0x47 - 0x46 (W1)], YA_ALARM [0x49 - 0x48 (W1)], ZA_ALARM [0x4B - 0x4A (W1)] and the alarm indication is registered in FLAG [0x06 (W0)], displayed in **ALARM_ERR** of bit [4:2]. Reading **ALARM_ERR** will reset the alarm display.

4.9. Structural Resonance Warning

If strong vibration is applied at the structural resonance frequency band, which is outside the measurement band (see Cantilever Resonance Frequency in Table 1.3 Sensor Specifications), the input signal is amplified excessively due to the structural resonance of the cantilever beam, and measurement cannot be performed properly. Therefore, notification is made via the structural resonance warning flag when the measurement value becomes abnormal, and at the same time, the upper limit of the measurement range is output as the sensor value instead of the measurement value for warning.

The structural resonance warning notification is displayed on **EXI_ERR** in Register: FLAG [0x06(W0)], bit [7:5] and on **EXI_ERR** in Register: TEMP2 [0x2E(W0)], bit [7:5]. Reading **EXI_ERR** will reset the warning notification.

The structural resonance level determination function provided in the self test is useful for determining possible countermeasures against structural resonance. Refer to "4.7 Self Test" for details.

4.10. Checksum

A checksum can be appended to the response data during UART/SPI Burst mode or UART Auto sampling by enabling this function in **CHKSM_OUT** (BURST_CTRL [0x0C(W1)], bit [0]).

The range of the data content for checksum is after the address byte (AD = 0x80) of the response data (Figure 4.8). The checksum is calculated with a simple addition of the data content in units of 16-bit, and the resulting sum is truncated to 16-bits and appended as checksum just before delimiter byte (CR = 0x0D). Note that in the case of UART Burst Mode and UART Auto sampling, the upper word of the sensor data of each axis is 8 bits, these data should be added in 8 bits.

Example 1) when the response data for UART Auto sampling is "8E00 0700 FF FFD8 00 007E 00 0296 1730", the total sum is "8E00+0700+FF+FFD8+00+007E+00+0296+1730=1B01B" resulting in a checksum of "B01B".

Example 2) when the response data for SPI Burst Mode is "8E00 0572 0000 0A33 FFFF F75D FFFF F18F 39E6 C075", the sum is "8E00+0572+0000+0A33+FFFF+F75D+FFFF+F18F+39E6=4C075" resulting in a checksum of "C075".

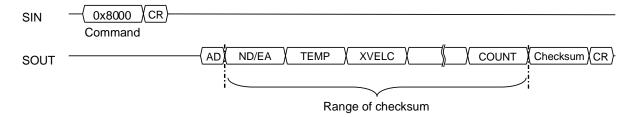


Figure 4.8 Checksum

4.11. Automatic Start (For UART Auto Sampling Only)

Automatic Start function is designed to be used in conjunction with the UART Auto sampling. When the power is supplied or the device is restart/reset, it allows the device to automatically enter Sampling mode after completing internal initialization. Please refer to Figure 4.3 for the state transition.

Follow the procedures below to enable the Automatic Start function:

- Write a "1" to both UART_AUTO (bit [0]) and AUTO_START (bit [1]) of UART_CTRL [0x08(W1)].
- Store the current register settings to non-volatile memory by writing a "1" to FLASH_BACKUP (GLOB_CMD [0x0A(W1)], bit [3]). After completion of the FLASH_BACKUP command, confirm the results by FLASH_BU_ERR (DIAG_STAT1 [0x04(W0)], bit [0]).
- The device will automatically enter Sampling Mode after the power supply is cycled, or a hardware reset, or a software reset command is executed.

Follow the procedures below to disable this function.

- After entering sampling mode with automatic start, write "01" to MODE_CMD of register: MODE_CTRL [0x02 (W0)], bit [9:8] and enter the configuration mode.
- Write "0" to AUTO_START of register: UART_CTRL [0x08 (W1)], bit [1].
- The subsequent steps are the same as above to store the register setting to nonvolatile memory and restart or reset the device.

4.12. Intermittent Measurement for Total Current Reduction

This explains how to realize intermittent measurement for reducing the device current consumption. The user can realize the intermittent measuremet by one of the methods below.

- (1) Method of using a sleep mode
- (2) Method of switching the device power directly on and off

Table 4.1 shows a summary of some essential items and characteristics.

Table 4.1 Summary of Intermittent Measurement Characteristics and Parameters

	(1) Using sleep mode	(2) Device power on and off
Switching method	Controlling a register and an EXT pin.	Switching the M-A352 power directly on and off
Current consumption at standby	1.3 mA Typ.	0 mA
Wakeup time	16 ms Max.	900 ms Max.
Advantage	Short wakeup time from sleep mode to sampling mode	Minimum current consumption at standby (power off)

Disadvantage	-	Necessity for design considerations to correctly handle floating device interface pins, or unpowered pins during standby mode (power off) and transition current at wakeup (power on)
Example of intended use	Event-driven measurement	Occasional measurement and long standby (power off) time

Note) When returning to sampling mode, current consumption increases from a low level to the typical current at sampling mode. This causes an increase in internal heating of the device resulting in a transitional increase in temperature compensation errors.

Note) The extent of the errors depends on many variables such as standby time, environment conditions, etc, therefore, the user should evaluate carefully these effects when used for strict and high precision measurement scenarios.

(1) Method of using sleep mode

The sleep mode function can be enabled by register setting. When shifting to sleep mode, internal circuit operation stops and current consumption during standby mode can be reduced to 1.3 mA (Typ.). Wakeup time from sleep mode to sampling mode can be shorter than that from power on to start time (reduced from 900 ms to 16 ms).

Put the operation mode from configuration mode into sleep mode by writing "11" to **MODE_CMD** (MODE_CTRL [0x02(W0)], bit [9:8]). The device can wake up from sleep mode to configuration mode in Sleep Wake-up Time by detecting an edge trigger on the EXT pin. Timing sequence from configuration mode to sleep mode and vice versa are shown in Figure 4.9.

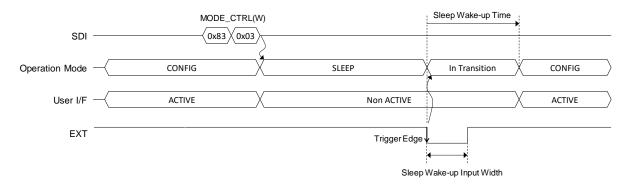


Figure 4.9 Timing Sequence from Configuration Mode to Sleep Mode and Vice Versa

(2) Method of switching the device power directly on and off

When the device power is directly switched on and off, the current consumption during standby mode can be 0 mA. Wakeup time from standby to sampling mode is exactly the same as that from power on to start time (900 ms). Please refer to "4.2 Operation Mode" for timing sequence from the power on to sampling mode.

Note) The communication interface pins shown in Table 1.6 will be un-powered during standby (the device power being off), and transition current will appear at wakeup time (device power on). The system interface to the device may need additional design considerations to mitigate the effects, i.e. an unpowered device input pin appears as a short circuit to GND to the host system or when the device is powered on before the system interface to these pins are driven (floating input).

4.13. Frequency Response Characteristics

The frequency response characteristics of this device are shown in Figure 4.10 and Figure 4.11.

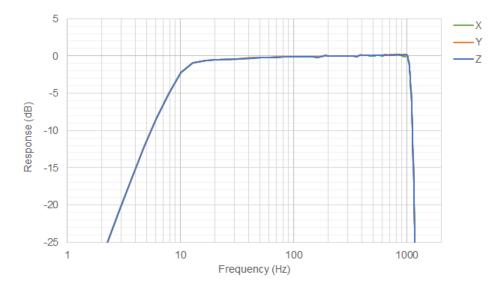


Figure 4.10 Frequency Response Characteristics (Velocity Output)

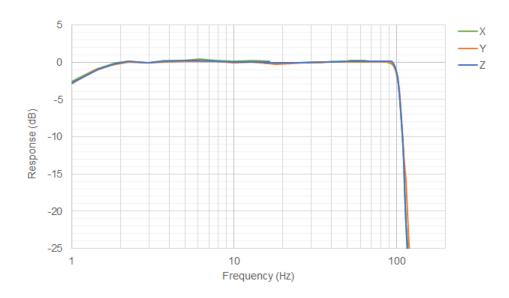


Figure 4.11 Frequency Response Characteristics (Displacement Output)

To achieve the above frequency response characteristics, two FIR filters (512-tap BPF, 256-tap HPF) are used in this product. For this reason, the transient response of the filters is produced at the start of measurement. During this period, the velocity value register: VELC [0x3A-0x30(W0)] and the displacement value register: DISP [0x3A-0x30(W0)] are not updated. In the case of UART Auto measurement, the output starts after the number of transient response samples elapses from the start of measurement. Table 4.2 shows the total transient response time of FIR filters at the start of measurement.

Table 4.2 Transient Response Time of FIR filters at the Start of Measurement

Output physical quantity	Transient response time
Velocity	0.177 s Typ. *1
Displacement	1.736 s Typ. *1

^{*1)} The initialization duration is included.

4.14. Velocity and Displacement Output

Either velocity output or displacement output can be selected in this product. The velocity output is calculated in the time domain by integrating the acceleration data measured by the crystal acceleration sensor. Displacement output is calculated by double integrating the acceleration data.

Instead of the velocity / displacement raw data output, you can also select to output velocity / displacement RMS (effective value) or P-P (peak-to-peak value). The RMS data is the root mean square of the velocity or displacement RAW data calculated for each of the 16 taps, averaged over the interval of **UPDATE_RATE_RMSPP** in Register: SMPL_CTRL [0x04(W1)], bit [7:0], and output in the interval of **DOUT_RATE_RMSPP** in Register: SMPL_CTRL [0x04(W1)], bit [15:8]. P-P data is calculated as the difference between the maximum and minimum values of velocity or displacement data in the time interval of **UPDATE_RATE_RMSPP** and output in the time interval of **DOUT_RATE_RMSPP**.

(1) Transient Response of Integral Filter

Note that when starting measurement, or when the sensor placement attitude changes considerably for some reason, there will be a transient response in the integral filter output due to bias fluctuation. Figures 4.12-15 show examples of transient responses.

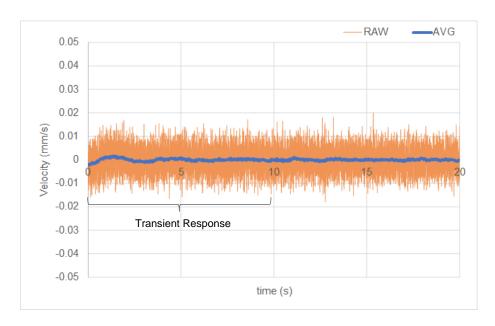


Figure 4.12 Example of Integral Filter Transient Response at the Start of Measurement (Velocity Output)

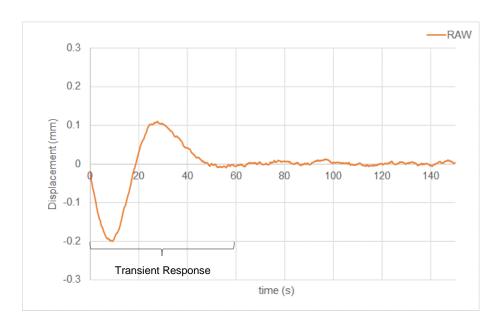


Figure 4.13 Example of Integral Filter Transient Response at the Start of Measurement (Displacement Output)

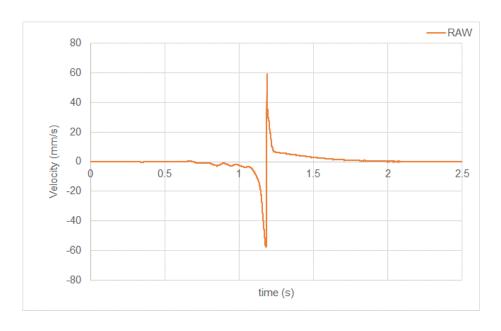


Figure 4.14 Example of Integral Filter Transient Response at 90° Change in Placement Attitude (Velocity Output)

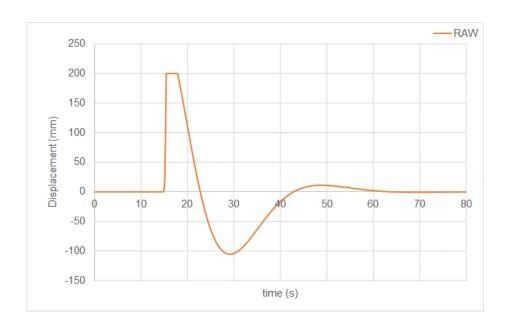


Figure 4.15 Example of Integral Filter Transient Response at 90° Change in Placement Attitude (Displacement Output)

(2) How to switch the output physical quantity

The factory default setting is velocity output. To switch the output physical quantity, set the desired output physical quantity in **OUTPUT_SEL** of the register: SIG_CTRL [0x00(W1)], bit [7:4]. After writing to **OUTPUT_SEL**, **OUTPUT_STAT** at bit [0] changes to "1" (running), and when the setting is complete, **OUTPUT_STAT** returns to "0". For the setting duration, refer to Output Mode Setting Time in Table 1.4 Interface Specifications.

Note) Do not write to the registers while the output physical quantity is being switched.

Note) If the switching of the output physical quantity fails, the setting will not be changed and an error will be displayed in **HARD_ERR** of the register: DIAG_STAT1 [0x04(W0)], bit [7:5].

4.15. Alignment Compensation

By reading alignment compensation coefficients stored in the dedicated registers and applying alignment compensation by the host on the measured values, the 3-axis alignment accuracy can be improved.

The procedure for reading the alignment correction coefficients and the formulas for the alignment compensation are as follows.

(1) Formulas for applying alignment compensation

$$Px = M_xD_x + M_{xy}D_y + M_{xz}D_z$$

$$Py = M_{yx}D_x + M_yD_y + M_{yz}D_z$$

$$Pz = M_{zx}D_x + M_{zy}D_y + M_zD_z$$

- *1) P: Alignment compensated values, M: Alignment compensation coefficients (32 bit), D: Measured values (32 bit)
- *2) Alignment compensation coefficient data format

32-bit two's complement format

bit 31 : sign bit 30 ~ 23 : integer bit 22 ~ 0 : decimal

- (2) Alignment compensation coefficients read-out procedure
 - 1. First, set the coefficient address to ALIGN ADDR in Register: ALIGNMENT_COEF_ADDR [0x3C(W1)], bit [7:0].
 - 2. Next, write "0x01" (Read) to **ALIGN_CMD** in Register: ALIGNMENT_COEF_CMD [0x38(W1)] bit [1:0] to perform coefficient reading.
 - 3. Next, read the coefficient data (16 bits) from **ALIGN_DATA** in Register: ALIGNMENT_COEF_DATA [0x3A(W1)], bit [15:0]. When the reading is completed, the address is automatically incremented, thus enabling continuous execution of the reading command (step 2).

The reading sequence (Figure 4.16) and the memory map of the coefficients (Table 4.3) are shown below.

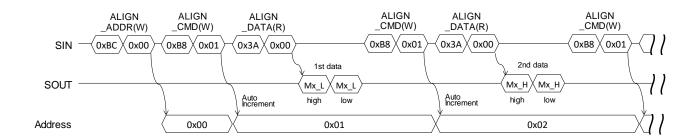


Figure 4.16 Alignment Compensation Coefficient Reading Sequence

Address	Coffecient Data	Address	Coffecient Data	Address	Coffecient Data
0x00	Mx_L	0x06	Myx_L	0x0C	Mzx_L
0x01	Mx_H	0x07	Myx_H	0x0D	Mzx_H
0x02	Mxy_L	0x08	My_L	0x0E	Mzy_L
0x03	Mxy_H	0x09	My_H	0x0F	Mzy_H
0x04	Mxz_L	0x0A	Myz_L	0x10	Mz_L
0x05	Mxz H	0x0B	Mvz H	0x11	Mz H

Table 4.3 Alignment Compensation Coefficients Memory Map

5. Digital Interface

This device has the following two external interfaces.

- (1) SPI interface
- (2) UART interface

The SPI interface and the UART interface have almost the same functions, except for Auto sampling function for the UART interface. No hardware pin configuration is necessary for SPI/UART selection since both interfaces are always active. Connect desired interface pins to SPI or UART interface.

Note) Connecting both SPI and UART at the same time is not supported and may result in malfunction of the device.

The registers inside the device are accessed via the SPI or UART interfaces.

In this document, data sent to the device is called a "Command" and data sent back in response to the command is called a "Response". There are two types of commands: write command and read command. The write command has no response. The write command always writes to the internal register in 8-bit words. The response to the read command, i.e. the data from the internal register, is always read in 16-bit words.

When reading from the registers, there is a burst mode in addition to the normal mode.

When the output data size is large, it may exceed the bandwidth of the host interface and cause the data transmission to be incorrect. In this case, the user must balance the transmission data rate and the bandwidth capability of the host interface.

Adjust the following settings accordingly to optimize the host interface bandwidth:

- For the UART, adjust the baud rate in BAUD_RATE (UART_CTRL [0x08(W1)], bit [9:8]).
- For the SPI, adjust the host side SPI clock frequency and SPI wait time.

Adjust the following settings accordingly to optimize the transmission data rate:

• The transmission data rate is also affected by the number of output bytes included in burst mode read transfer. The adjustment to the number of output bytes is in registers BURST_CTRL [0x0C(W1)].

Several concrete examples for setting the transmission data rate and host interface bandwidth are shown below. For the selection of the read out mode for the host interface bandwidth, refer to "5.4 Recommended Control Conditions".

(1) For UART Output:

- ① When the output data size is small (output data example: Temperature, XYZ)
- BAUD_RATE ="01" of UART CTRL [0x08(W1)], bit [9:8]: 460800 baud
- UART_AUTO ="1" of UART CTRL [0x08(W1)], bit [0]: UART Auto sampling
- BURST_CTRL [0x0C(W1)] = "0x4700": TEMP and Velocity-XYZ output
- When the output data size is large (output data example: Flag, temperature, XYZ, COUNT, checksum)
- BAUD RATE ="00" of UART CTRL [0x08(W1)], bit [9:8]: 921600 baud
- UART_AUTO ="1" of UART CTRL [0x08(W1)], bit [0]: UART Auto sampling
- BURST_CTRL [0x0C(W1)] = "0xC703": FLAG, TEMP, Velocity-XYZ, COUNT, and CHECKSUM output

(2) For SPI Output:

- SPI Interface Transmission Setting: f_{SCLK} = 2 MHz, t_{STALL1} = 45 μs, t_{STALL2} = 0 μs for burst mode
- UART_AUTO ="0" of UART_CTRL [0x08(W1)], bit [0]: UART Manual sampling
- BURST_CTRL [0x0C(W1)] = "0x4702": TEMP, Velocity-XYZ and COUNT output

5.1. SPI Interface

Table 5.1 shows the communication settings of SPI interface and Table 5.2 shows the SPI timing for normal mode.

Table 5.1 SPI Communication Settings

Parameter	Setting
Mode	Slave
Word length	16 bits
Phase	Rising Edge
Polarity	Negative Logic

Table 5.2 SPI Timing (Normal Mode)

Parameter	Minimum	Maximum	Unit
fsclk	0.01	2.0	MHz
t _{STALL}	20	-	μs
twriterate	40	-	μs
t _{READRATE}	28	-	μs

5.1.1. SPI Read Timing (Normal Mode)

The response data to a read command, i.e. the data from the internal register, is always returned in 16-bit words. The SPI interface supports sending the next command during the same bus cycle as receiving a response to the read command (full-duplex).

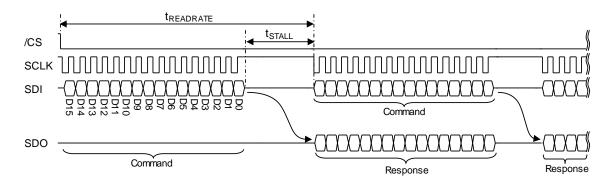


Figure 5.1 SPI Read Timing (Normal Mode)

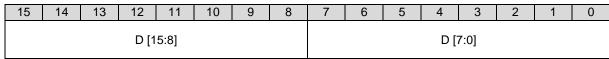
Table 5.3 Command Format (Read)

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	A [6:0]									Х	X				

A [6:0] ··· Register address (even address)

XX ... Don't Care

Table 5.4 Response Format (Read)



D [15:8] ··· Register read data (upper byte)
D [7:0] ··· Register read data (lower byte)

5.1.2. SPI Write Timing (Normal Mode)

A write command to a register has no response. Unlike register reading, registers are written in 8-bit words.

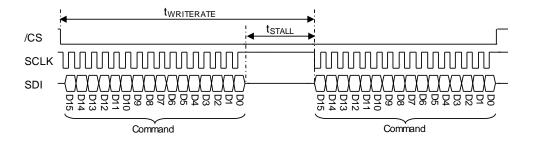


Figure 5.2 SPI Write Timing (Normal Mode)

Table 5.5 Command Format (Write)

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
1				A [6:0]							D [7	7:0]			

A [6:0] ··· Register address (even or odd number)

D [7:0] ··· Register write data

5.1.3. SPI Read Timing (Burst Mode)

Burst mode access of read data is supported using a "Burst Read Command" by writing 0x00 in **BURST_CMD** (BURST [0x00(W0)], bit [7:0]). In burst mode, ND flag/EA flag, temperature value, 3-axis velocity value, etc. are consecutively sent as a response. The response format for the burst read output data is configured by register setting in BURST_CTRL [0x0C(W1)]. Please refer to 5.3 Data Packet Format for the response format.

Table 5.6 SPI Timing (Burst Mode)

Parameter	Minimum	Maximum	Unit
fsclk	0.01	2.0	MHz
tstall1	45	-	μs
tstall2	0	-	μs
treadrate2	8	-	μs

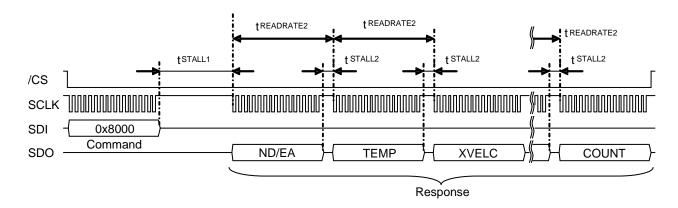


Figure 5.3 SPI Read Timing (Burst Mode)

5.2. UART Interface

Table 5.7 shows the supported UART communication settings and Figure 5.4 shows the UART bit format. Please refer to **BAUD_RATE** (UART_CTRL [0x08(W1)], bit [9:8]) for changing the baud rate setting.

Table 5.7 UART Communication Settings

Parameter	Settings
Transfer rate	115.2 kbps / 230.4 kbps / 460.8 kbps / 921.6 kbps
Start	1 bit
Data	8 bits
Stop	1 bit
Parity	None
Delimiter	CR (0x0D)

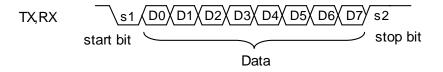


Figure 5.4 UART Bit Format

For the UART interface, a delimiter (1 byte) is placed at the end of each command (by the host) and response (by this device). In addition for responses, the address (1 byte) specified by the command is added (by this device) to the beginning of the response.

Table 5.8 and Table 5.9 shows the timing of UART.

Table 5.8 UART Timing

	Norma	al Mode	Manual	Sampling	Auto S	ampling	
Parameter	INOITII	ii ivioue	Burst	Mode	Auto	Mode	Unit
	Min.	Max.	Min.	Max.	Min.	Max.	
tstall	-	25	-	50	-	- *2	μs
twriterate (115.2 kbps)	660	-	-	-	660	-	μs
twriterate (230.4 kbps)	350	•	-	-	350		μs
twriterate (460.8 kbps)	200	-	-	-	200	-	μs
twriterate (921.6 kbps)	130	-	-	-	130	-	μs
treadrate (115.2 kbps)	660	•	*1	-	- *2		μs
treadrate (230.4 kbps)	350	ı	*1	-	- *2	•	μs
treadrate (460.8 kbps)	200	-	*1	-	- *2	-	μs
treadrate (921.6 kbps)	130	-	*1	-	- *2	-	μs

^{*1)} Please refer to Table 5.9.

Table 5.9 UART Timing (treadrate requirements for Burst Mode)

Parameter	Burst Mode (Min.)	Unit
treadrate (115.2 kbps)	660 + 86.8 × B	μs
treadrate (230.4 kbps)	350 + 43.4 × B	μs
treadrate (460.8 kbps)	200 + 21.7 × B	μs
t _{READRATE} (921.6 kbps)	130 + 10.9 × B	μs

B = Number of receive data bytes (AD: address and CR: delimiter is not included).

Example tREADRATE Calculation:

BURST_CTRL [0x0C(W1)]: Set value 0x4700

B = 11 byte for the above stated register setting

 $t_{READRATE}$ (460.8 kbps) = 200 + (21.7 × 11) = 438.7 (µs)

^{*2)} Register reading is not supported while in Sampling Mode with UART Auto Sampling enabled.

5.2.1. UART Read Timing (Normal Mode)

The response to the read command, i.e. the data from the internal register, is always returned 16-bit data at a time. The register address (AD) comes at the beginning of the response, for example, 0x02 for the MODE_CTRL [0x02(W0)] register.

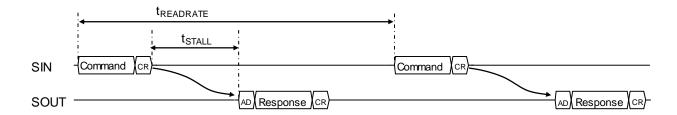


Figure 5.5 UART Read Timing (Normal Mode)

Table 5.10 Command Format (Read)

		The	e fir	st b	yte				Т	he s	sec	ond	byt	е				The	thi	rd b	yte		
7	7 6 5 4 3 2 1 0								7 6 5 4 3 2 1 0								6	5	4	3	2	1	0
0	0 A[6:0]										X	Χ							0x	0D			

A [6:0] ··· Register address (even address)

XX ··· Don't Care 0x0D ··· Delimiter

Table 5.11 Response Format (Read)

			The	e fir	st b	yte				Т	he:	sec	ond	byt	е				The	e thi	rd b	yte				-	The	fou	rth I	byte)	
7	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
(0			Α	[6:0	0]					I	D [1	5:8							D [7	7:0]							0x	0D			

A [6:0] ··· Register address (even address)
D [15:8] ··· Register read data (upper byte)

D [7:0] ··· Register read data (lower byte)

0x0D · · · Delimiter

5.2.2. UART Read Timing (Burst Mode)

Burst mode access of read data is supported using a "Burst Read Command" by writing 0x00 in **BURST_CMD** (BURST [0x00(W0)], bit [7:0]). In Burst Mode, ND/EA flag, temperature value, 3-axis velocity value, etc. are consecutively sent as a response. The response format for the burst read output data is configured by register setting in BURST_CTRL [0x0C(W1)]. Please refer to 5.3 Data Packet Format for the response format.

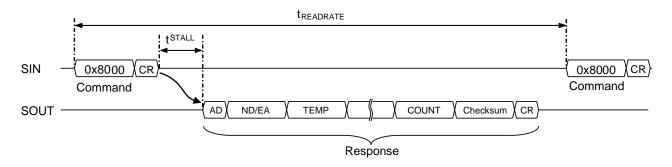


Figure 5.6 UART Read Timing (Burst Mode)

Table 5.12 Command Format (Burst Mode)

		The	e fir	st b	yte				T	he:	sec	ond	byt	е				The	thi :	rd b	yte		
7	9	5	4	3	2	1	0	7	9	5	4	З	2	1	0	7	6	5	4	З	2	1	0
			0x	80							0x	00							0x0	0D			

0x80 ··· Burst Command 0x00 ··· Burst Data 0x00 0x0D ··· Delimiter

5.2.3. UART Write Timing

A write command to a register will have no response. Unlike register reading, registers are written in 8-bit words.

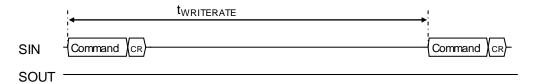


Figure 5.7 UART Write Timing

Table 5.13 Command Format (Write)

		The	e fir	st b	yte				Т	he:	sec	ond	byt	е				The	thi	rd b	yte		
7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
1			Α	[6:0	0]						D [7	7:0]							0x0	0D			

A [6:0] ··· Register address (even or odd number)

D [7:0] · · · Register write data

0x0D · · · Delimiter

5.2.4. UART Auto Sampling Operation

When UART Auto sampling is active, all sensor outputs are sent as burst transfer automatically at the programmed output data rate without the request from the Host. For information about the response format, see 5.3 UART Data Packet Format. The response format for the burst read output data is configured by register setting in BURST_CTRL [0x0C(W1)].

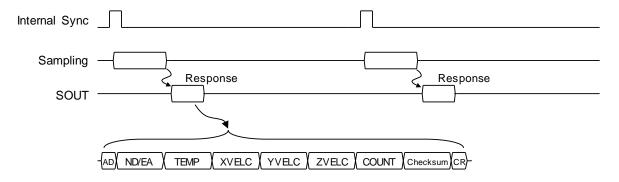


Figure 5.8 UART Auto Sampling

5.3. Data Packet Format

The following table shows example of the data packet format sent to the host in the UART Burst Mode or UART Auto Sampling and SPI burst mode.

Table 5.14 Example of Data Packet Format 1 (UART BURST / AUTO SAMPLING)

 $\begin{aligned} & \texttt{BURST_CTRL} \ [0x0C(W1)] = 0xC703 \ (\texttt{Burst Output: FLAG, TEMP, Velocity-XYZ, COUNT, CHECKSUM)} \\ & \texttt{SIG_CTRL} \ [0x00(W1)] = 0x8E02 \ (\texttt{Output Mode: Velocity, TEMP1)} \end{aligned}$

Byte No.	Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0				
1	ADDRESS				0x	80							
2	ND	ND (Temp)	-	-	-	ND (XVELC)	ND (YVELC)	ND (ZVELC)	-				
3	EA	X_EXI _ERR	Y_EXI _ERR	Z_EXI _ERR	XALARM _ERR	YALARM _ERR	ZALARM _ERR	-	EA				
4	TEMP1_H				TEMP	1 [15:8]							
5	TEMP1_L				TEMP	1 [7:0]							
6	XVELC_HIGH_L				XVELC _I	HIGH [7:0]							
7	XVELC_LOW_H XVELC_LOW [15:8]												
8	XVELC_LOW_L XVELC _LOW [7:0]												
9	YVELC_HIGH_L YVELC _HIGH [7:0]												
10	YVELC_LOW_H				YVELC _L	.OW [15:8]							
11	YVELC_LOW_L				YVELC _	LOW [7:0]							
12	ZVELC_HIGH_L				ZVELC _I	HIGH [7:0]							
13	ZVELC_LOW_H				ZVELC _L	.OW [15:8]							
14	ZVELC_LOW_L				ZVELC _I	LOW [7:0]							
15	COUNT_H				COUN	T [15:8]							
16	COUNT_L				COUN	IT [7:0]							
17	CHECKSUM_H				CHECKS	UM [15:8]							
18	CHECKSUM_L				CHECKS	SUM [7:0]							
19	CR				0x	0D							

Table 5.15 Example of Data Packet Format 2 (UART BURST / AUTO SAMPLING)

 $\begin{aligned} & \text{BURST_CTRL} \ [0\text{x0C(W1)}] = 0\text{x4700} \ (\text{Burst Output: TEMP, Velocity-XYZ}) \\ & \text{SIG_CTRL} \ [0\text{x00(W1)}] = 0\text{x8E00} \ (\text{Output Mode: Velocity, TEMP2}) \end{aligned}$

Byte No.	Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
1	ADDRESS				0x	80				
2	TEMP2_H		TEMP2 [15:8]							
3	TEMP2_L		TEMP2 [7:0]							
4	XVELC_HIGH_L		XVELC _HIGH [7:0]							
5	XVELC_LOW_H		XVELC_LOW [15:8]							
6	XVELC_LOW_L		XVELC _LOW [7:0]							
7	YVELC_HIGH_L				YVELC _H	HIGH [7:0]				
8	YVELC_LOW_H				YVELC _L	.OW [15:8]				
9	YVELC_LOW_L				YVELC _I	LOW [7:0]				
10	ZVELC_HIGH_L				ZVELC _H	HIGH [7:0]				
11	ZVELC_LOW_H				ZVELC _L	.OW [15:8]				
12	ZVELC_LOW_L		ZVELC _LOW [7:0]							
13	CR				0x	0D			_	

Table 5.16 Example of Data Packet Format 3 (SPI BURST MODE)

BURST_CTRL [0x0C(W1)] = 0xC703 (Burst Output: FLAG, TEMP, Velocity-XYZ, COUNT, CHECKSUM) SIG_CTRL [0x00(W1)] = 0x8E02 (Output Mode: Velocity, TEMP1)

Word No.	Bit15		Bit0								
1		FLAG (ND/EA)									
2		TEMP1									
3		XVELC_HIGH (The upper byte is reserved.)									
4		XVELC_LOW									
5		YVELC _HIGH (The upper byte is reserved.)									
6		YVELC _LOW									
7		ZVELC _HIGH (The upper byte is reserved.)									
8		ZVELC _LOW									
9		COUNT									
10		CHECKSUM									

Table 5.17 Example of Data Packet Format 4 (SPI BURST MODE)

 $\begin{aligned} & \texttt{BURST_CTRL} \ [0x0C(W1)] = 0x4700 \ (\texttt{Burst Output: TEMP, Velocity-XYZ}) \\ & \texttt{SIG_CTRL} \ [0x00(W1)] = 0x8E00 \ (\texttt{Output Mode: Velocity, TEMP2}) \end{aligned}$

Word No.	Bit15		Bit0							
1		TEMP2								
2		XVELC_HIGH (The upper byte is reserved.)								
3		XVELC_LOW								
4		YVELC _HIGH (The upper byte is reserved.)								
5		YVELC _LOW								
6		ZVELC _HIGH (The upper byte is reserved.)								
7		ZVELC _LOW								

5.4. Recommended Communication Conditions

5.4.1. Selection of Communication Condition for UART

To ensure that the output data bandwidth does not exceed the bandwidth capability of the host UART interface, select the output physical quantity, output data size, communication speed, and read out mode respectively according to the purpose of use. Table 5.18 and Table 5.19 show the selection matrices for typical output data sizes.

When sampling velocity RAW output with the maximum data size (19 Bytes), only 921.6 kbps is available for a communication speed. In particular, when sampling the velocity RAW output with the initial data size (13 bytes), communication at 460.8 kbps is available in AUTO mode (not available when reading out in BURST mode).

Table 5.18 Communication Condition Selection Matrix for UART 1

Output data size: Max.19 Bytes (Addr + Flag + Temp + X + Y + Z + Count + CS + CR)

Output physical	Readout mode		Communica	ation speed	
quantity	Readout mode	921.6 kbps	460.8 kbps	230.4 kbps	115.2 kbps
Velocity RAW	AUTO	OK	-	-	-
(3000 Šps)	BURST	OK	-	-	-
Velocity RMS/P-P	AUTO	OK	OK	OK	OK
(10 Sps ~)	BURST	OK	OK	OK	OK
Displacement RAW	AUTO	OK	OK	OK	OK
(300 Sps)	BURST	OK	OK	OK	OK
Displacement	AUTO	OK	OK	OK	OK
RMS/P-P (1 Sps ~)	BURST	ОК	OK	OK	ОК

Table 5.19 Communication Condition Selection Matrix for UART 2

Output data size: Default 13 Bytes (Addr + Temp + X + Y + Z + CR)

Output physical	Readout mode		Communication speed						
quantity	Readout mode	921.6 kbps	460.8 kbps	230.4 kbps	115.2 kbps				
Velocity RAW	AUTO	OK	OK ^(*1)	-	-				
(3000 Šps)	BURST	OK	-	-	-				
Velocity RMS/P-P	AUTO	OK	OK	OK	OK				
(10 Sps ~)	BURST	OK	OK	OK	OK				
Displacement RAW	AUTO	OK	OK	OK	OK				
(300 Sps)	BURST	OK	OK	OK	OK				
Displacement	AUTO	OK	OK	OK	OK				
RMS/P-P (1 Sps ~)	BURST	OK	OK	OK	ОК				

^{*1)} Factory default setting.

5.4.2. Selection of Communication Condition for SPI

To ensure that the output data bandwidth does not exceed the bandwidth capability of the host SPI interface, select the output physical quantity, output data size, communication speed, and read out mode respectively according to the purpose of use. Table 5.20 shows the selection matrix for typical output data sizes.

For velocity RAW output, communication at the highest speed is preferred as shown in the recommended timing conditions in Table 5.20. In all other cases, there is no recommended condition.

Table 5.20 Communication Condition Selection Matrix for SPI

BURST Output data size: Max. 20 Bytes (Flag + Temp + X + Y + Z + Count + Checksum) NORMAL Output data size: Max.18 Bytes (Flag + Temp + X + Y + Z + Count)

Output physical	Readout mode	fso	CLK	Recommended Timing Conditions						
quantity	Readout mode	2MHz	1MHz	tstall	treadrate	tstall1	tstall2	treadrate2		
Velocity RAW	BURST	OK	OK	-	-	45	0	8		
(3000 Sps)	NORMAL	OK	-	20	28	-	-	-		
Velocity RMS/P-P	BURST	OK	OK							
(10 Sps ~)	NORMAL	OK	OK							
Displacement RAW	BURST	OK	OK			*4				
(300 Sps)	NORMAL	OK	OK	*1						
Displacement	BURST	OK	OK							
RMS/P-P (1 Sps ~)	NORMAL	OK	OK							

^{*1)} There is no recommended condition.

User Register

A host device (for example, a microcontroller) can control the device by accessing the control registers inside the device.

The registers are accessed in this device using a WINDOW method. The prescribed window number is first written to WINDOW_ID of WIN_CTRL [0x7E(W0/W1)], bit [7:0], then the desired register address can be accessed. The WIN_CTRL [0x7E(W0/W1)] register can always be accessed without needing to set the window number.

During the Power-On Start-Up Time or the Reset Recovery time specified in the Table 1.4 Interface Specifications, all the register values are undefined because internal initialization is in progress. Ensure the device registers are only accessed after the Power-On Start-Up Time or the Reset Recovery time is over.

For information about the initial values of the control registers after internal initialization is finished, see the "Default" column in the Table 6.1. The control registers with O mark in the "Flash Backup" column can be saved to the non-volatile memory by the user, and the initial values after the power on will be the values read from the non-volatile memory. If the read out from the non-volatile memory fails, the **FLASH_ERR** (DIAG_STAT1 [0x04(W0)], bit [2]) is set to 1 (error).

Please ensure that the device is in the Configuration Mode before writing to registers. In the Sampling Mode, writing to registers is ignored except for the following cases.

- MODE_CMD in MODE_CTRL [0x02(W0)], bit [9:8]
- SOFT_RST in GLOB_CMD [0x0A(W1)], bit [7]
- WINDOW_ID in WIN_CTRL [0x7E(W0/W1)], bit [7:0]

While in the UART Auto Mode with Sampling Mode is active, register read access is not supported. Otherwise, the sampling data transmitted in the UART Auto Mode will be corrupted by the response data from the register read.

Each register is 16-bit wide and one address is assigned to every 8 bits. Registers are read in 16-bit words and are written in 8-bit words. The byte order of each 16-bit register is little endian, but the byte order of the 16-bit data transferred over the digital interface is big endian.

Table 6.1 shows the register map, and Section 6.1 through Section 6.28 describes the registers in detail.

The "-" sign in the register assignment table in Section 6.1 through Section 6.28 means "reserved".

Write a "0" to reserved bits during a write operation.

During a read operation, a reserved bit can return either 0 or 1 ("don't care").

Writing to a read-only register is prohibited.

Note) The explanation of the register notation MODE_CTRL [0x02(W0)], bit [9:8] is as follows:

- MODE_CTRL: Register name
- [0x02(W0)]: First number is the Register Address, (W0) means Window Number "0"
- bit [9:8]: Bits 9 to 8

Table 6.1 Register Map

Name	Window ID	Address	(*3) Read Command 16bit Read	Write Command 8bit Write	R/W	Flash Backup	Default	Function
BURST	0	0x00 0x01	-	0x80 -	W -	_	-	Burst mode
MODE_CTRL	0	0x02 0x03	0x02XX	- 0x83	- R/W	_	0x00 0x04	Operation mode control
DIAG_STAT1	0	0x04 0x05	0x04XX	-	R R	_	0x00 0x00	Diagnostic result 1
FLAG	0	0x06 0x07	0x06XX	-	R R	_	0x00 0x00	ND/EA flag
COUNT	0	0x0A 0x0B	0x0AXX	-	R R	_	0x00 0x00	Sampling count
DIAG_STAT2	0	0x0C 0x0D	0x0CXX	-	R R	_	0x00 0x00	Diagnostic result 2
TEMP1	0	0x10 0x11	0x10XX	-	R R	_	0xFF 0xFF	Temperature value 1
ACC_SELFTEST _DATA1	0	0x2A 0x2B	0x2AXX	-	R R	_	0xFF 0xFF	Self test acceleration value1 (X-axis)
ACC_SELFTEST _DATA2	0	0x2C 0x2D	0x2CXX	-	R R	_	0xFF 0xFF	Self test acceleration Value2 (Y, Z-axis)
TEMP2	0	0x2E 0x2F	0x2EXX	-	R R	_	0xFF 0x00	Temperature value 2
1) XVELC_HIGH 2) XDISP_HIGH	0	0x30 0x31	0x30XX	-	R R	_	0xFF 0xFF	X Velocity High X Displacement High
1) XVELC_LOW 2) XDISP_LOW	0	0x32 0x33	0x32XX	-	R R	_	0xFF 0xFF	1) X Velocity Low 2) X Displacement Low
1) YVELC_HIGH 2) YDISP_HIGH	0	0x34 0x35	0x34XX	-	R R	_	0xFF 0xFF	1) Y Velocity High 2) Y Displacement High
1) YVELC_LOW	0	0x36	0x36XX	-	R	_	0xFF	1) Y Velocity Low
2) YDISP_LOW 1) ZVELC_HIGH	0	0x37 0x38	0x38XX	-	R R	_	0xFF 0xFF	Y Displacement Low Z Velocity High
2) ZDISP_HIGH 1) ZVELC_LOW	1	0x39 0x3A		-	R R		0xFF 0xFF	Z Displacement High Z Velocity Low
2) ZDISP_LOW	0	0x3B 0x00	0x3AXX	- 0x80	R R/W	-	0xFF 0x00	2) Z Displacement Low
SIG_CTRL	1	0x01 0x02	0x00XX	0x81 0x82	R/W R/W	0	0x8E 0x26	ND flag control Output mode control
MSC_CTRL	1	0x03 0x04	0x02XX	0x83 0x84	R/W R/W	0	0x00 0x07	DataReady signal & polarity control
SMPL_CTRL	1	0x05 0x08	0x04XX	0x85 0x88	R/W R/W	0	0x0A 0x01	Sampling control
UART_CTRL	1	0x09 0x0A	0x08XX	0x89 0x8A	R/W R/W	0	0x01 0x00	UART control
GLOB_CMD	1	0x0B 0x0C	0x0AXX	- 0x8C	R/W	-	0x00 0x00	System control
BURST_CTRL ALIGNMENT	1	0x0D 0x38	0x0CXX	0x8D 0xB8	R/W R/W	0	0x47 0x00	Burst control Alignment correction
_COEF_CMD ALIGNMENT	1	0x39 0x3A	0x38XX	-	- R	-	0x00 0x00	coefficient readout control Alignment correction
_COEF_DATA ALIGNMENT	1	0x3B 0x3C	0x3AXX	- 0xBC	R R/W	-	0x00 0x00	coefficient Alignment correction
_COEF_ADDR	1	0x3D 0x46	0x3CXX	- 0xC6	- R/W	-	0x00 0x66	coefficient readout address
XALARM	1	0x47	0x46XX	0xC7	R/W	0	0x06	X alarm threshold value

WIN_CTRL	0,1	0x7F	UX/EAA	-	-	_	0x00	Register Window Contro	
WIN CTDI	0.1	0x7E	0x7EXX	0xFE	R/W		0x00	Pagistar Window Control	
SENIAL_NUM4	1	0x7B	UXTAXX	-	R			Serial Number 4	
SERIAL_NUM4	1	0x7A	0x7AXX	-	R	_		Serial Number 4	
SERIAL_NUM3	1	0x79	0x78XX	-	R			Serial Number 3	
CEDIAL NUM2	1	0x78	0.70	-	R	_		Serial Number 3	
SERIAL_NUM2	1	0x77	0x76XX	-	R			Serial Number 2	
CEDIAL NUMO	4	0x76	070\/\	-	R			Carial Number 0	
SERIAL_NUM1	1	0x75	0x74XX	-	R] -	(*2)	Serial Number 1	
CEDIAL NUMA	4	0x74	074\/\/	-	R			Firmware version	
VERSION	1	0x73	0x72XX	-	R	_	(')		
PROD_ID4	1	0x72	070	-	R		(*1)	F	
	1	0x71	0x70XX	-	R	_	0x30	Product ID 4	
DDOD ID4	_	0x70	070)()(-	R		0x31	December 1D 4	
PROD_ID3	1	0x6F	0x6EXX	-	R	_	0x44	Product ID 3	
DDOD IDO		0x6E	0.05107	-	R		0x56	D 1 1/D 0	
PROD_ID2	1	0x6D	0x6CXX	-	R	_	0x32	Product ID 2	
DDOD IDO		0x6C	0.00004	-	R		0x34	D 1 1/D 0	
PROD_ID1	1	0x6B	0x6AXX	-	R	-	0x33	Product ID 1	
	_	0x6A		-	R		0x41		
ZALARM	1	0x4B	0x4AXX	0xCB	R/W	0	0x06	Z alarm threshold value	
	_	0x4A		0xCA	R/W		0x66		
YALARM	1	0x49	0x48XX	0xC9	R/W	0	0x06	Y alarm threshold value	
	_	0x48		0xC8	R/W	_	0x66		

^{* 1)} This depends on the version of the installed firmware.
* 2) This is determined by each individual serial number.

^{* 3)} Lower byte XX: Do not care

6.1. BURST Register (Window 0)

Addr (Hex)	Bit15		Bit8	R/W
0x01		-		-

Addr (Hex)	Bit7		Bit0	R/W
0x00		BURST_CMD		W

bit [7:0] BURST_CMD

A burst mode read operation is initiated by writing 0x00 in BURST_CMD of this register.

Note) The data transmission format is described in 5.1.3 SPI Read Timing (Burst Mode) and 5.2.2 UART Read Timing (Burst Mode). Also refer to 5.3 Data Packet Format. The output data can be selected by setting BURST_CTRL [0x0C(W1)].

6.2. MODE_CTRL Register (Window 0)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x03	-	-	-	-	MODE_STAT		MODE	_CMD	R/W *1

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x02	-	-	-	-	-	-	-	-	-

^{*1)} MODE_STAT is read-only.

bit [11:10] MODE_STAT

This read-only status bit shows the current operation mode.

- 00: Sampling Mode
- 01: Configuration mode
- 10: Sleep Mode
- 11: (Not Used)

bit [9:8] MODE_CMD

Executes commands related to the operation mode.

- 00: Execute Complete.
- 01: Go to the Sampling Mode.
 - After the mode transition is completed, the bits automatically goes back to "00".
- 10: Go to the Configuration Mode.
 - After the mode transition is completed, the bits automatically goes back to "00".
- 11: Go to the Sleep Mode.
 - After the mode transition is completed, the bits automatically goes back to "00".
- Note) The UART and SPI interfaces cannot be used during sleep mode. To wake up from sleep mode, input an edge trigger to the EXT pin. The internal circuits of the device will recover to nomal operation by the EXT trigger, and operation state will return from sleep mode to configuration mode.

6.3. DIAG_STAT1 Register (Window 0)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x05	ACC_VEC _ERR	ACC_X _ERR	ACC_Y _ERR	ACC_Z _ERR	-	-	TEMP _ERR	VDD _ERR	R

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x04		HARD _ERR		SPI _OVF	UART _OVF	FLASH _ERR	ACC_ERR _ALL	FLASH_ BU_ERR	R

Note) When the host reads the diagnosis result, all the results (including the EA flag in the FLAG register) will be cleared to 0.

bit [15] ACC_VEC_ERR (ACC VECtor magnitude ERRor)

Shows the execution result of vector magnitude value of acceleration three axes in ACC_TEST of MSC_CTRL [0x02 (W1)], bit [10].

- 1: Error occurred
- 0: No error

If this error occurs, sensor is faulty.

bit [14] ACC_X_ERR

Shows the result of X axis sensor operation check in ACC_TEST of MSC_CTRL [0x02 (W1)], bit [10].

- 1: Error occurred
- 0: No error

If this error occurs, X axis sensor is faulty.

bit [13] ACC_Y_ERR

Shows the result of Y axis sensor operation check in ACC_TEST of MSC_CTRL [0x02 (W1)], bit [10].

- 1: Error occurred
- 0: No error

If this error occurs, Y axis sensor is faulty.

bit [12] ACC_Z_ERR

Shows the result of Z axis sensor operation check in ACC_TEST of MSC_CTRL [0x02 (W1)], bit [10].

- 1: Error occurred
- 0: No error

If this error occurs, Z axis sensor is faulty.

bit [9] TEMP_ERR

Shows the execution result of TEMP_TEST (Temp Sensor Check) of MSC_CTRL [0x02 (W1)], bit [9].

- 1: Error occurred
- 0: No error

If this error occurs, temperature sensor is faulty.

bit [8] VDD_ERR

Shows the execution result of VDD_TEST (Power Supply Voltage Check) of MSC_CTRL [0x02 (W1)], bit [8].

- 1: Error occurred
- 0: No error

If this error occurs, Check whether the power supply voltage level is within the specified range.

bit [7:5] HARD_ERR

Shows the result of the hardware check at startup. Any abnormality in the setting of **OUTPUT_SEL** of SIG_CTRL [0x00(W1)], bit [7:4] is also reflected in this bit.

Other than 000: Error occurred

000: No error

When this error occurs, it indicates the device is faulty.

bit [4] SPI_OVF (SPI OVer Flow)

Shows an error occurred if the device received too many commands from the SPI interface in short period of time.

- 1: Error occurred
- 0: No error

When this error occurrs, review the SPI command transmission interval and the SPI clock setting.

bit [3] UART OVF (UART OVer Flow)

Shows an error occurred if the data transmission rate is faster than the UART baud rate.

- 1: Error occurred
- 0: No error

When this error occurs, review the settings for the baud rate (register: UART_CTRL [0x08(W1)], bit [9:8]), UART Burst Mode/Auto sampling (register: BURST_CTRL [0x0C(W1)]) in combination.

bit [2] FLASH_ERR

Shows the result of **FLASH_TEST** of MSC_CTRL [0x02(W1)], bit [11].

1: Error occurred

0: No error

This error indicates a failure occurred when reading data out from the non-volatile memory.

bit [1] ACC_ERR_ALL (ACCTest ERRor All)

Shows the logical sum of bit [15:12] of this register.

- 1: Error occurred
- 0: No error

bit [0] FLASH_BU_ERR (FLASH BackUp ERRor)

Shows the result of **FLASH_BACKUP** of GLOB_CMD [0x0A(W1)], bit [3].

- 1: Error occurred
- 0: No error

6.4. FLAG (ND/EA) Register (Window 0)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x07	ND (Temp)	-	ı	1	ND (XVELC) (XDISP)	ND (YVELC) (YDISP)	ND (ZVELC) (ZDISP)	ı	R

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x06	X_EXI _ERR	Y_EXI _ERR	Z_EXI _ERR	XALARM _ERR	YALARM _ERR	ZALARM _ERR	-	EA	R

Note) **EXI_ERR** flags and **ALARM_ERR** flags are cleared to "0" by reading this register. Note that in Burst mode and UART Auto sampling, these flags are cleared to "0" after every sample output regardless of the **FLAG_OUT** setting in regster BURST_CTRL, bit [15].

Note) In case a structural resonance warning is issued, when normal mode is selected, the upper limit of the measurement range is output as the sensor value instead of the measured value until **EXI_ERR** in Register: FLAG [0x06(W0)], bit [7:5] is read out.

Note) EA flag is cleared to "0" by reading the DIAG_STAT1 register.

bit [15] ND (New Data) flag (Temperature)

When new measurement data is set in temperature register (TEMP1 [0x10(W0)], TEMP2 [0x2E(W0)]), this bit is set to "1". This bit is reset to "0" reading by the temperature register.

bit [11:9] ND (New Data) flag (Velocity/Displacement)

When new measurement data is set in velocity register (XVELC_HIGH [0x30(W0)], YVELC_HIGH [0x34(W0)], ZVELC_HIGH [0x38(W0)]) or displacement register (XDISP_HIGH [0x30(W0)], YDISP_HIGH [0x34(W0)],

ZDISP_HIGH [0x38(W0)]), this bit is set to "1". This bit is reset to "0" by reading the velocity/displacement register.

bit [7] X_EXI_ERR

This bit indicates when the measured value of X-axis becomes abnormal due to structural resonance in the sensor.

- 1: Measurement value is abnormal due to structural resonance
- 0: Measured value is within normal range

bit [6] Y_EXI_ERR

This bit indicates when the measured value of Y-axis becomes abnormal due to structural resonance in the sensor.

- 1: Measurement value is abnormal due to structural resonance
- 0: Measured value is within normal range

bit [5] Z EXI ERR

This bit indicates when the measured value of Z-axis becomes abnormal due to structural resonance in the sensor.

- 1: Measurement value is abnormal due to structural resonance
- 0: Measured value is within normal range

bit [4] XALARM_ERR

This bit indicates when the sensor value exceeds the value set in register: X_ALARM [0x47-0x46(W1)] in the X axis during measurement.

1: detection

0: no detection

bit [3] YALARM_ERR

This bit indicates when the sensor value exceeds the value set in register: Y_ALARM [0x49-0x48(W1)] in the Y axis during measurement.

1: detection

0: no detection

bit [2] ZALARM ERR

This bit indicates when the sensor value exceeds the value set in register: Z_ALARM [0x4B-0x4A(W1)] in the Z axis during measurement.

- 1: detection
- 0: no detection

bit [0] EA (All Error) flag

When at least one failure is found in the diagnostic result (DIAG_STAT1 [0x04(W0)]), this bit is set to "1" (failure occurred). This bit is reset to "0" by reading the DIAG STAT1 register.

- 1: Failure occurred
- 0: No Failure

6.5. COUNT Register (Window 0)

Addr (Hex)	Bit15		Bit0	R/W
0x0A		COUNT		R

bit [15:0] COUNT

This register returns the sampling count value of the internal Analog Front End.

Note) The time unit of the sampling counter value represents:

velocity: $1/6000 \text{ Sps} = 167 \text{ }\mu\text{s/count}$ displacement: 1/600 Sps = 1.67 ms/count

For RAW data output, the values are 2, 4, 6, ..., 65534, 0, 2,

For Velocity 1 Sps RMS/P-P data output, the values are 6002, 12002, 18002,

6.6. DIAG_STAT2 Register (Window 0)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x0D	-	-	Z_EXI_	LEVEL	Y_EXI_	LEVEL	X_EXI_	LEVEL	R

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x0C	-	-	-	-	-	-	-	-	1

Note) When the host reads the diagnosis result, all the results will be cleared to 0.

bit [13:12] Z EXI LEVEL (Z EXcessive Input LEVEL)

Shows the diagnosis result of Z axis for **EXI_TEST** (Structural Resonance Level Test) of register: MSC_CTRL [0x02(W1)], bit [15]. The diagnosis details for each level are shown in Table 6.2.

00: Diagnosis result: OK (structural resonance level: allowable range)

01: Diagnosis result: NG (structural resonance level: large)

10: Reserved

11: Reserved

bit [11:10] Y_EXI_ LEVEL (Y EXcessive Input LEVEL)

Shows the diagnosis result of Y axis for **EXI_TEST** (Structural Resonance Level Test) of register: MSC_CTRL [0x02(W1)], bit [15]. The contents of the Diagnosis result are the same as those of **Z_EXI_LEVEL**.

bit [9:8] X_EXI_ LEVEL (X EXcessive Input LEVEL)

Shows the diagnosis result of X axis for **EXI_TEST** (Structural Resonance Level Test) of register: MSC_CTRL [0x02(W1)], bit [15]. The contents of the Diagnosis result are the same as those of **Z_EXI_LEVEL**.

Table 6.2 Diagnosis Details for Each Structural Resonance Level

Diagnosis result	Structural resonance level	Descriptions
OK	allowable range	Ready for use with intended performance.
NG	large	Intended performance may not be achieved. The mounting method and/or installation location are recommended to be reconsidered.

6.7. TEMP1 Register (Window 0)

Addr (Hex)	Bit15		Bit0	R/W	
0x10		16BIT_TEMP		R	

bit [15:0] Temperature sensor output data (16bit)

The internal temperature sensor value can be read from this register.

The output data format is 16-bit two's complement format.

Please refer to the below formula for conversion to temperature in centigrade. Please refer to Table 1.3 Sensor Specification for the scale factor value.

There is no guarantee that the value provides the absolute value of the internal temperature.

$$T_{16bit}$$
 (°C) = $SF_{16bit} \times a + 34.987$

SF: Scale Factor

a: Temperature sensor output data (decimal)

6.8. ACC_SELFTEST_DATA1 Register (Window 0)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W	
0x2B		X_ACC_DATA								
Addr	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W	

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x2A				ACC_	_VEC				R

bit [15:8] X_ACC_DATA

The X-axis acceleration value of ACC_TEST of register: MSC_CTRL [0x02(W1)], bit [10] can be read from this register.

The output data format

Unit: (m/s²)

8-bit two's complement format

bit 7 : sign bit 6 ~ 2 : integer bit 1 ~ 0 : decimal

 $0.25 (m/s^2)/LSB$

bit [7:0] ACC_VEC (ACC VECtor magnitude)

The 3-axis acceleration vector magnitude value of **ACC_TEST** of register: MSC_CTRL [0x02(W1)], bit [10] can be read from this register. The output data format is the same as that of **X_ACC_DATA**.

Note) If the measured value exceeds the readout range, the upper or lower limit of the readout range is stored. +31.75 m/s² or higher, "0x7F" is stored. -31.75 m/s² or lower, "0x81" is stored.

6.9. ACC_SELFTEST_DATA2 Register (Window 0)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W	
0x2D		Z_ACC_DATA								
Addr (Hex)	Bit7	Bit7 Bit6 Bit5 Bit4 Bit3 Bit2 Bit1 Bit0								

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x2C		Y_ACC_DATA							R

bit [15:8] Z ACC DATA

The Z-axis acceleration value of **ACC_TEST** of register: MSC_CTRL [0x02(W1)], bit [10] can be read from this register. The output data format is the same as that of **X_ACC_DATA**.

bit [7:0] Y_ACC_DATA

The Y-axis acceleration value of **ACC_TEST** of register: MSC_CTRL [0x02(W1)], bit [10] can be read from this register. The output data format is the same as that of **X_ACC_DATA**.

6.10. TEMP2 Register (Window 0)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x2F		8BIT_TEMP							R

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x2E	X_EXI _ERR	Y_EXI _ERR	Z_EXI _ERR	XALARM _ERR	YALARM _ERR	ZALARM _ERR	2BIT_0	COUNT	R

Note) **EXI_ERR** flags and **ALARM_ERR** flags are cleared to "0" by reading this register. Note that in Burst mode and UART Auto sampling, these flags are cleared to "0" after every sample output regardless of the **TEMP_OUT** setting in regster BURST_CTRL, bit [14]. These flags have the same function as those in the FLAG (ND/EA) register. However, the flag states are not linked and needs to be cleared separately.

Note) In case a structural resonance warning is issued, when normal mode is selected, the upper limit of the measurement range is output as the sensor value instead of the measured value until **EXI_ERR** in Register: FLAG [0x06(W0)], bit [7:5] is read out.

bit [15:8] 8BIT_TEMP Temperature sensor output data (8 bits)

The internal temperature sensor value can be read from this register.

The output data format is 8-bit two's complement format.

Please refer to the below formula for conversion to temperature in centigrade. Please refer to Table 1.3 Sensor Specification for the scale factor value.

There is no guarantee that the value provides the absolute value of the internal temperature.

$$T_{8bit}$$
 (°C) = SF_{8bit} × a + 34.987

SF: Scale Factor

a: Temperature sensor output data (decimal)

bit [7] X_EXI_ERR

This bit indicates when the measured value of X-axis becomes abnormal due to structural resonance in the sensor.

- 1: Measurement value is abnormal due to structural resonance
- 0: Measured value is within normal range

bit [6] Y_EXI_ERR

This bit indicates when the measured value of Y-axis becomes abnormal due to structural resonance in the sensor.

- 1: Measurement value is abnormal due to structural resonance
- 0: Measured value is within normal range

bit [5] Z_EXI_ERR

This bit indicates when the measured value of Z-axis becomes abnormal due to structural resonance in the sensor.

- 1: Measurement value is abnormal due to structural resonance
- 0: Measured value is within normal range

bit [4] XALARM_ERR

This bit indicates when the sensor value exceeds the value set in register: X_ALARM [0x47-0x46(W1)] in the X axis during measurement.

- 1: detection
- 0: no detection

bit [3] YALARM_ERR

This bit indicates when the sensor value exceeds the value set in register: Y_ALARM [0x49-0x48(W1)] in the Y axis during measurement.

- 1: detection
- 0: no detection

bit [2] ZALARM_ERR

This bit indicates when the sensor value exceeds the value set in register: Z_ALARM [0x4B-0x4A(W1)] in the Z axis during measurement.

- 1: detection
- 0: no detection

bit [1:0] 2BIT_COUNT

A 2-bit count value that counts up at each sampling count.

6.11. VELC Register (Window 0)

Addr (Hex)	Bit15		Bit8	Bit7		Bit0	R/W			
0x30		-			XVELC_HIGH_L					
0x32		XVELC_LOW_H			XVELC_LOW_L	-	R			
0x34		-			R					
0x36		YVELC_LOW_H			-	R				
0x38		-			-	R				
0x3A		ZVELC_LOW_H				R				

bit [15:0] Velocity output data

These registers contain the 3-axis velocity data (RAW, RMS, P-P) for X, Y, and Z.

The output data format

Unit (m/s)

24-bit two's complement format

bit 23 : sign bit 22 : integer bit 21 ~ 0 : decimal

Note) Velocity, and displacement readout addresses are the same.

Note) When the velocity value exceeds the preset threshold value, reading velocity value responds with the threshold value. For example, if the preset threshold values are set to +100 mm/s and -100 mm/s, the corresponding response is "0x066666" for +100 mm/s or more, and "0xF9999A" for -100 mm/s or less.

Note) The velocity output rate is fixed at 3000 Sps. RMS/P-P output rate can be set by **DOUT_RATE_RMSPP** in Register: SMPL_CTRL [0x04(W1)], bit [15:8].

6.12. DISP Register (Window 0)

Addr (Hex)	Bit15		Bit8	Bit7		Bit0	R/W	
0x30		-			XDISP_HIGH_L	•	R	
0x32		XDISP_LOW_H			XDISP_LOW_L		R	
0x34		-			R			
0x36		YDISP_LOW_H				R		
0x38		-		ZDISP_HIGH_L				
0x3A		ZDISP_LOW_H			R			

bit [15:0] Displacement output data

These registers contain the 3-axis displacement data (RAW, RMS, P-P) for X, Y, and Z.

The output data format

Unit (m)

24-bit two's complement format bit 23 : sign

bit 22 : integer bit 21 ~ 0 : decimal

Note) Velocity, and displacement readout addresses are the same.

Note) When the displacement value exceeds the preset threshold value, reading displacement value responds with the threshold value. For example, if the preset threshold values are set to +200 mm and -200 mm, the corresponding response is "0x0CCCCC" for +200 mm or more, and "0xF33334" for -200 mm or less.

Note) The displacement output rate is fixed at 300 Sps. RMS/P-P output rate can be set by **DOUT_RATE_RMSPP** in Register: SMPL_CTRL [0x04(W1)], bit [15:8].

6.13. SIG_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x01	ND_EN (Temp)	-	-	-	ND_EN (XVELC) (XDISP)	ND_EN (YVELC) (YDISP)	ND_EN (ZVELC) (ZDISP)	-	R/W

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x00		OUTPL	JT_SEL		0	-	TEMP _SEL	OUTPUT _STAT	R/W

bit [15] ND_EN (Temp)

Enables or disables the temperature sensor ND flags in FLAG [0x06(W0)], bit [15].

- 1: Enable
- 0: Disable

bit [11] ND EN (X-axis sensor)

Enables or disables the X-axis sensor ND flags in FLAG [0x06(W0)], bit [11].

- 1: Enable
- 0: Disable

bit [10] ND_EN (Y-axis sensor)

Enables or disables the Y-axis sensor ND flags in FLAG [0x06(W0)], bit [10].

- 1: Enable
- 0: Disable

bit [9] ND_EN (Z-axis sensor)

Enables or disables the Z-axis sensor ND flags in FLAG [0x06(W0)], bit [9].

- 1: Enable
- 0: Disable

bit [7:4] OUTPUT_SEL

Sets the output physical quantity of the XYZ axis sensor.

0000: Velocity RAW

0001: Velocity RMS

0010: Velocity P-P

0011: Reserved

0100: Displacement RAW

0101: Displacement RMS

0110: Displacement P-P

0111 - 1111: Reserved

bit [3] Reserved to 0

This bit must be fixed to 0.

bit [1] TEMP_SEL

Specify the temperature format to be output in Burst Mode and UART Auto sampling.

- 0: Temperature format 2 (8-bit temperature + EXI_ERR flags + ALARM_ERR flags + 2-bit counter)
- 1: Temperature format 1 (16-bit temperature)

bit [0] OUTPUT_STAT

Indicates the setting status of the output physical quantity **OUTPUT_SEL**. This bit is read-only.

- 1: Setting in progress
- 0: Setting complete

Note) If the **OUTPUT_SEL** setting fails, the setting will not be changed and an error will be displayed in **HARD_ERR** of register: DAIG_STAT1 [0x04(W0)], bit[7:5]

Note) When the output physical quantity **OUTPUT_SEL** is set, do not write to the register until the setting is completed. For the setting time of the output physical quantity, refer to Output Mode Setting Time in Table 1.4 Interface Specifications.

6.14. MSC_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x03	EXI _TEST	-	-	-	FLASH _TEST	ACC _TEST	TEMP _TEST	VDD _TEST	R/W

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x02	-	0	EXT _POL	-	-	DRDY _ON	DRDY _POL	-	R/W

Note) Although ACC_TEST, TEMP_TEST, and VDD_TEST can be executed at the same time, other tests cannot be executed at the same time. When executing them in succession, confirm the execution of the previous command is finished by waiting until the bit changes from "1" to "0" and then execute the next command.

bit [15] EXI_TEST

The structural resonance level test for all three axes is executed simultaneously by writing "1" to this bit. This bit displays "1" during execution, and returns to "0" when completed. After writing "1" to this bit, confirm that this bit returns to "0", and then check **EXI_ERR** in the register: DIAG_STAT2 [0x0C(W0)], bits [13:8] to confirm the diagnosis result.

Note) This structural resonance level test cannot be run with other tests at the same time.

bit [11] FLASH_TEST

Write "1" to execute the data consistency test for the non-volatile memory. The read value of the bit is "1" during the test and "0" after the test is completed. After writing "1" to this bit, wait until this bit goes back to "0" and then read the **FLASH_ERR** of DIAG_STAT1 [0x04(W0)], bit [2] to check the result.

Note) This flash memory test cannot be run with other tests at the same time.

bit [10] ACC_TEST

Write "1" to execute the self test to check if the X, Y, and Z axis sensor is working properly. The read value of the bit is "1" during the test and "0" after the test is completed. After writing "1" to this bit, wait until this bit goes back to "0" and then read the ACC_ERR_ALL of DIAG_STAT1 [0x04(W0)], bit [1] to check the results.

bit [9] TEMP_TEST

Write "1" to execute the self test to check if temperature sensor is working properly. The read value of the bit is "1" during the test and "0" after the test is completed. After writing "1" to this bit, wait until this bit goes back to "0" and then read the **TEMP_ERR** of DIAG_STAT1 [0x04(W0)], bit [9] to check the results.

bit [8] VDD_TEST

Write "1" to execute the self test to check if power supply voltage level is working properly. The read value of the bit is "1" during the test and "0" after the test is completed. After writing "1" to this bit, wait until this bit goes back to "0" and then read the **VDD_ERR** of DIAG_STAT1 [0x04(W0)], bit [8] to check the results.

bit [6] Reserved to 0

This bit must be fixed to 0.

bit [5] EXT_POL

Selects the polarity of the EXT terminal (Recovery from Sleep Mode).

- 1: Negative logic (falling edge)
- 0: Positive logic (rising edge)

bit [2] DRDY_ON

Selects the function of the DRDY terminal, when set to "1", Data Ready signal is output.

- 1: Data Ready Signal is enabled
- 0: Data Ready Signal is disabled

bit [1] DRDY_POL

Selects the polarity of the Data Ready signal when selected in **DRDY_ON** above.

- 1: Active High
- 0: Active Low

6.15. SMPL_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x05				DOUT_RAT	ΓE_RMSPP				R/W

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x04	-	-	-	-	ι	JPDATE_RA	ATE_RMSPF	Þ	R/W

Note) For a detailed description of output and update rate, refer to 4.14 Velocity and Displacement Output.

bit [15:8] DOUT_RATE_RMSPP

Sets the output rate for RMS and P-P data. The setting format is as follows.

Table 6.3 and 6.4 show setting examples.

Setting range $n = 1 \sim 255$

Output rate (s) Velocity: $0.1 \times n$

Displacement: 1 × n

bit [7:0] UPDATE_RATE_RMSPP

Sets the update rate for RMS and P-P data. The setting format is as follows.

Table 6.3 and 6.4 show setting examples.

Setting range $n = 0 \sim 15$

Update rate (s) Velocity: $1/3000 \times 16 \times 2^{n}$

Displacement: 1/300 × 16 × 2ⁿ

Note) The update rate and output rate of the RAW data are fixed (velocity: 3000 Sps, displacement: 300 Sps).

Table 6.3 Mapping of Output Rate and Update Rate to Setting Values (Velocity)

	ΓE_RMSPP ut rate	UPDATE_RATE_RMSPP Update rate		
(s)	Setting values	(s)	Setting values	
0.1	1	0.0853	4	
0.2 - 0.3	2 - 3	0.1706	5	
0.4 - 0.6	4 - 6	0.3413	6	
0.7 - 1.3	7 - 13	0.6826	7	
1.4 - 2.7	14 - 27	1.3653	8	
2.8 - 5.4	28 - 54	2.7306	9	
5.5 - 10.9	55 - 109	5.4613	10	
11.0 - 21.8	110 - 218	10.922	11	
21.9 - 25.5	219 - 255	21.845	12	

Table 6.4 Mapping of Output Rate and Update Rate to Setting Values (Displacement)

DOUT_RAT	ΓE_RMSPP	UPDATE_RA	ATE_RMSPP
Outpu	ıt rate	Updat	te rate
(s)	Setting values	(s)	Setting values
1	1	0.853	4
2 - 3	2 - 3	1.706	5
4 - 6	4 - 6	3.413	6
7 - 13	7 - 13	6.826	7
14 - 27	14 - 27	13.653	8
28 - 54	28 - 54	27.306	9
55 - 109	55 - 109	54.613	10
110 - 218	110 - 218	109.22	11
219 - 255	219 - 255	218.45	12

6.16. UART_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x09				-			BAUD <u>.</u>	_RATE	R/W

Addr (Hex)	Bit7		Bit2	Bit1	Bit0	R/W
0x08		-		AUTO _START	UART _AUTO	R/W

bit [9:8] BAUD RATE

These bits specifies the Baud Rate of UART interface.

00: 921.6 kbps 01: 460.8 kbps 10: 230.4 kbps 11: 115.2 kbps

Note) The baud rate change using these BAUD_RATE bits become effective immediately after write access completes.

bit [1] AUTO_START (Only valid for UART Auto sampling)

Enables or disables the Auto Start function.

- 1: Automatic Start is enabled
- 0: Automatic Start is disabled

When Auto Start is enabled, the device enters sampling mode and sends sampling data automatically after completing internal initialization after powered on.

Write a "1" to this AUTO_START bit and UART_AUTO bit of this register to enable this function. Then execute FLASH_BACKUP of GLOB_CMD [0x0A(W1)], bit [3] to preserve the current register settings.

bit [0] UART_AUTO

Enables or disables the UART Auto sampling function.

- 1: UART Auto sampling is selected
- 0: UART Manual sampling is selected

If UART Auto sampling is active, register values such as flag, temperature, and velocity are continuously transmitted automatically. In UART Manual sampling, register data is transmitted as a response to a register read command.

Note) This register bit must be set to 0 when using the SPI interface.

Note) For more info on UART Auto sampling refer to 5.2.4 UART Auto Sampling Operation and 5.3 Data Packet Format. The burst output data is configured by register setting in BURST_CTRL [0x0C(W1)].

6.17. GLOB_CMD Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x0B	-	-	-	-	-	NOT _READY	-	-	R

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x0A	SOFT _RST	1	-	-	FLASH_ BACKUP	FLASH _RST	-		R/W

bit [10] NOT_READY

Indicates whether this product currently ready. Immediately after power on, this bit is "1" and becomes "0" when the product is ready. After the power on, wait until the Power-On Start-Up Time has elapsed and then wait until this bit becomes "0" before starting sensor measurement. This bit is read-only.

- 1: Not ready
- 0: Ready

bit [7] SOFT_RST

Write "1" to execute software reset, and wait until the Reset Recovery Time has elapsed. After the software reset is completed, the bit automatically goes back to "0".

bit [3] FLASH_BACKUP

Write "1" to save the current values of the control registers with the O mark in the "Flash Backup" column of

Table 6.1 to the non-volatile memory. After the execution is completed, the bit automatically goes back to "0" and then check the result in $FLASH_BU_ERR$ of DIAG_STAT1 [0x04(W0)], bit [0].

bit [2] FLASH_RST

Write "1" to resets the setting value saved in the nonvolatile memory to the factory default state. After completion of execution, it will automatically return to "0". After confirming this bit goes back to "0" and then check the result in **FLASH_BU_ERR** of DIAG_STAT1 [0x04(W0)], bit [0]. The factory default state will be reflected to the registers after completing internal initialization after powered on or a reset.

6.18. BURST_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x0D	FLAG _OUT	TEMP _OUT	-	-	-	SENSOR _X_OUT	SENSOR _Y_OUT	SENSOR _Z_OUT	R/W

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x0C	-	-	-	-	-	-	COUNT _OUT	CHKSM _OUT	R/W

These bits enable/disable the content in the output data for burst mode and UART Auto sampling.

bit [15] FLAG_OUT

Controls the output of FLAG status.

- 1: Enables output.
- 0: Disables output.

bit [14] TEMP_OUT

Controls the output of temperature sensor.

The output mode is selected by **TEMP_SEL** of register: SIG_CTRL [0x00 (W1)], bit [1].

- 1: Enables output.
- 0: Disables output.

bit [10] SENSOR_X_OUT

Controls the output of X axis sensor value (velocity/displacement).

The output mode is selected by OUTPUT_SEL of register: SIG_CTRL [0x00 (W1)], bit [7:4].

- 1: Enables output.
- 0: Disables output.

bit [9] SENSOR_Y_OUT

Controls the output of Y axis sensor value (velocity/displacement).

The output mode is selected by OUTPUT_SEL of register: SIG_CTRL [0x00 (W1)], bit [7:4].

- 1: Enables output.
- 0: Disables output.

bit [8] SENSOR_Z_OUT

Controls the output of Z axis sensor value (velocity/displacement).

The output mode is selected by OUTPUT_SEL of register: SIG_CTRL [0x00 (W1)], bit [7:4].

- 1: Enables output.
- 0: Disables output.

bit [1] COUNT_OUT

Controls the output of counter value.

- 1: Enables output.
- 0: Disables output.

bit [0] CHKSM_OUT

Controls the output of checksum.

- 1: Enables output.
- 0: Disables output.

Note) Please set "1: Enables output" to at least one bit of bit [10:8]. All outputs of sensor values cannot be disabled at the same time.

6.19. ALIGNMENT_COEF_CMD Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x39	-	-	-	-	-	-	-	-	-

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x38	-	-	-	-	-	-	ALIGN	I_CMD	R/W

bit [1:0] ALIGN_CMD

This is the control command for readout of the alignment compensation coefficients. For the readout procedure, refer to 4.15 Alignment Compensation.

For READ

00: execution complete
01: reading in progress
10: not used
11: not used

For WRITE
do nothing
read
not used
not used

6.20. ALIGNMENT_COEF_DATA Register (Window 1)

Addr (Hex)	Bit15		Bit0	R/W
0x3A		ALIGN_DATA		R

bit [15:0] ALIGN_DATA

This is the alignment compensation coefficient data register for reading from the correction coefficient storage memory. The data size of each coefficient is 32 bits, and the readout size is 16 bits. For the data format and the coefficient storage memory map, refer to 4.15 Alignment Compensation.

6.21. ALIGNMENT_COEF_ADDR Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W	
0x3D	-	-	-	-	-	-	-	-	-	
Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W	
0x3C		ALIGN_ADDR R								

bit [7:0] ALIGN ADDR

This is the address where the alignment compensation coefficient to be readout is stored.

Note) The address is automatically incremented after the control command for readout of the alignment compensation coefficients is executed.

Note) The setting range is from 0x0000 to 0x0011. It cannot be set outside the range.

6.22. X_ALARM Register (Window 1)

Addr (Hex)	Bit15	•	Bit0	R/W
0x46		XALARM		R/W

bit [15:0] XALARM

Set the upper limit value for evaluating **XALARM_ERR** in Register: FLAG [0x06(W0)], bit [4] and Register: TEMP2 [0x2E(W0)], bit [4]. The format and setting data range are as follows.

(1) For velocity RAW, velocity RMS, velocity P-P

Unit (m/s) 16-bit unsigned

bit 15 ~ 14 : integer
bit 13 ~ 0 : decimal
setting range : 0 ~ +100 mm/s

(2) For displacement RAW, displacement RMS, displacement P-P

Unit (m)

16-bit unsigned

bit 15 ~ 14 : integer bit 13 ~ 0 : decimal setting range : 0 ~ +200 mm

Note) If the upper limit is set beyond the setting range, the upper limit of the setting range will be used for evaluation.

Note) The upper limit value that is valid for the threshold detection can only be a positive number.

6.23. Y_ALARM Register (Window 1)

Addr (Hex)	Bit15	•	Bit0	R/W
0x48		YALARM		R/W

bit [15:0] YALARM

Set the upper limit value for evaluating **YALARM_ERR** in Register: FLAG [0x06(W0)], bit [3] and Register: TEMP2 [0x2E(W0)], bit [3]. The data format and setting range are the same as those of **X_ALARM**.

6.24. Z ALARM Register (Window 1)

Addr (Hex)	Bit15		Bit0	R/W
0x4A		ZALARM		R/W

bit [15:0] ZALARM_UP

Set the upper limit value for evaluating **ZALARM_ERR** in Register: FLAG [0x06(W0)], bit [2] and Register: TEMP2 [0x2E(W0)], bit [2]. The data format and setting range are the same as those of **X_ALARM**.

6.25. PROD ID Register (Window 1)

Addr (Hex)	Bit15		Bit0	R/W
0x6A		PROD_ID1		R
0x6C		PROD_ID2		R
0x6E		PROD_ID3		R
0x70		PROD_ID4		R

bit [15:0] Product ID

These registers return the product model number represented in ASCII code.

Product ID return value is A342VD10

PROD_ID1: 0x3341 PROD_ID2: 0x3234 PROD_ID3: 0x4456 PROD_ID4: 0x3031

6.26. VERSION Register (Window 1)

Addr (Hex)	Bit15		Bit0	R/W	
0x72		VERSION		R	l

bit [15:0] Version

This register returns the Firmware Version.

6.27. SERIAL_NUM Register (Window 1)

Addr (Hex)	Bit15		Bit0	R/W
0x74		SERIAL_NUM1		R
0x76		SERIAL_NUM2		R
0x78		SERIAL_NUM3		R
0x7A		SERIAL_NUM4		R

bit [15:0] Serial Number

These registers return the serial number represented in ASCII code.

For example, if the Serial Number is 01234567 then the return value is:

SERIAL_NUM1: 0x3130 SERIAL_NUM2: 0x3332 SERIAL_NUM3: 0x3534 SERIAL_NUM4: 0x3736

6.28. WIN_CTRL Register (Window 0,1)

Addr (Hex)	Bit15		Bit8	R/W
0x7F		-		-

Addr (Hex)	Bit7		Bit0	R/W
0x7E		WINDOW_ID		R/W

bit [7:0] WINDOW_ID

Selects the desired register window by writing the window number to this register.

0x00: Window 0 0x01: Window 1 0x02 ~ 0xFF: Unused

7. Sample Program Sequence

The following describes the recommended procedures for operating this device.

7.1. UART Sample Programs

```
7.1.1. Power-On Sequence (UART)
```

```
(a) Power on.
(b) Wait for the time specified by "Power-On Start-Up Time".
(c) Check NOT_READY in register: GLOB_CMD [0x0A(W1)], bit [10].
  Tx = {0xFE, 0x01, 0x0d}.
                                         /* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */
                                         /* Read out GLOB CMD */
  Tx = \{0x0A, 0x00, 0x0d\}.
                                         /* Retrieve the response value */
  Rx = \{0x0A, MSByte, LSByte, 0x0d\}.
  // if NOT_READY is 0, initialization is complete; if 1, initialization is in progress.
(d) Check HARD_ERR in register: DIAG_STAT1 [0x04(W0)], bit [7:5].
  Tx = \{0xFE,0x00,0x0d\}.
                                         /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
                                         /* Read out DIAG_STAT1 */
  Tx = \{0x04,0x00,0x0d\}.
  Rx = \{0x04, MSByte, LSByte, 0x0d\}.
                                         /* Retrieve the response value */
  // If HARD_ERR is 000, the hardware check completes successfully; if not, an error occurred.
```

7.1.2. Register Read and Write (UART)

Register Read Example

```
(a) Read 16-bit data from the register (Address = 0x02 / Window = 0).

Tx = {0xFE, 0x00, 0x0d}. /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
Tx = {0x02, 0x00, 0x0d}. /* Read out MODE_CTRL */
Rx = {0x02, 0x04, 0x00, 0x0d}. /* Retrieve the response value */
// The 2nd byte of Rx data "0x04" indicates a configuration mode.
// The 3rd byte of Rx data "0x00" indicates Reserved.
// Read data is by 16 bits with MSB first format.
```

Register Write Example

```
(a) Write 8-bit data to the register (Address = 0x03 / Window = 0).

Tx = {0xFE, 0x00, 0x0d}. /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */

Tx = {0x83, 0x01, 0x0d}. /* Write to MODE_CTRL (H) to go to Sampling mode */

// No corresponding response for data writing.

// Write data is by 8 bits
```

7.1.3. Configure Output Physical Quantity (UART)

```
(a) Write the output physical quantity and temperature format
                                          /* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */
  Tx = \{0xFE, 0x01, 0x0d\}.
  Tx = \{0x80, 0x00, 0x0d\}.
                                          /* Write to SIG_CTRL (L) to set output physical quantity = velocity RAW,
                                            temperature format 2 */
(b) Wait until the setting is completed.
  // Wait for the time specified in "Output Mode Setting Time",
  // Or verify OUTPUT_STAT of register: SIG_CTRL [0x00(W1)], bit [0] returns to 0 as shown below.
  Tx = \{0x00, 0x00, 0x0d\}.
                                          /* Read out SIG_CTRL */
                                         /* Retrieve the response value */
  Rx = \{0x00, MSByte, LSByte, 0x0d\}.
  // If OUTPUT_STAT is 0, the setting is complete; if 1, the setting is in progress and (b) needs to be repeated.
  // Note) Do not write to the register while the setting is being executed.
(c) Confirm the setting result.
  // Check HARD_ERR in register: DIAG_STAT1 [0x04(W0)], bit [7:5].
                                          /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
  Tx = \{0xFE, 0x00, 0x0d\}.
  Tx = \{0x04, 0x00, 0x0d\}.
                                          /* Read out DIAG_STAT1 */
  Rx = \{0x04, MSByte, LSByte, 0x0d\}.
                                         /* Retrieve the response value */
  // If HARD_ERR is 0, the settingis completes successfully; if 1, an error occurred.
```

7.1.4. Sampling (UART)

Auto sampling (example)

```
(a) Configure the sampling parameters (the following is an example of setting the factory defaults). Tx = {0xFE, 0x01, 0x0d}. /* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */
```

```
Tx = \{0x80, 0x00, 0x0d\}.
                                         /* Write to SIG_CTRL (L) to set output physical quantity = velocity RAW,
                                           temperature format 2 */
  // See Section 7.1.3 for details on the procedure for setting the output physical quantities.
  Tx = \{0x88, 0x01, 0x0d\}.
                                         /* Write to UART_CTRL (L) to set UART Mode = Auto sampling*/
  Tx = \{0x8C, 0x00, 0x0d\}.
                                         /* Write to BURST_CTRL (L) to set Burst counter = off, checksum = off */
  Tx = \{0x8D, 0x47, 0x0d\}.
                                         /* Write to BURST_CTRL (H) to set Burst flag = off, temp = on, sensor = on */
  Tx = \{0xC6, 0x66, 0x0d\}.
                                         /* Write to X ALARM (L) to set X detection threshold = 100 mm/s */
                                         /* Write to X_ALARM (H) */
  Tx = \{0xC7, 0x06, 0x0d\}.
  Tx = \{0xC8, 0x66, 0x0d\}.
                                         /* Write to Y_ALARM (L) to set Y detection threshold = 100 mm/s */
                                         /* Write to Y_ALARM (H) */
  Tx = \{0xC9, 0x06, 0x0d\}.
                                         /* Write to Z_ALARM (L) to set Z detection threshold = 100 mm/s */
/* Write to Z_ALARM (H) */
  Tx = \{0xCA, 0x66, 0x0d\}.
  Tx = {0xCB, 0x06, 0x0d}.
  Tx = \{0xFE, 0x00, 0x0d\}.
                                         /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
(b) Start sampling.
  Tx = \{0x83, 0x01, 0x0d\}.
                                         /* Write to MODE_CTRL (H) to go to Sampling mode */
  // Note) The transition duration from Configuration mode to Sampling mode, refer to "Sampling Start Time" in Table 1.4
          Interface Specifications.
  // Note) The transient response time (output hold time) of FIR filters, refer to Table 4.2 Transient response time of FIR filters
          at the start of measurement.
(c) Receive sampling data.
  Rx = \{0x80,
      TEMP2_H, TEMP2_L,
      XVCCL_HIGH_L, XVCCL_LOW_H, XVCCL_LOW_L,
      YVCCL_HIGH_L, YVCCL_LOW_H, YVCCL_LOW_L,
      ZVCCL_HIGH_L, ZVCCL_LOW_H, ZVCCL_LOW_L,
  // Repeat (c).
  // "XVCCL_HIGH_L" refers to the LSB byte of XVELC_HIGH data
  // "XVCCL_LOW_H" refers to the MSB byte of XVELC_LOW data
  // "XVCCL_LOW_L" refers to the LSB byte of XVELC_LOW data
(d) Stop sampling.
  Tx = \{0x83, 0x02, 0x0d\}.
                                         /* Write to MODE_CTRL (H) to go to Configuration mode */
  // Note) For the transition duration from Sampling mode to Configuration mode, refer to "Sampling Stop Time" in Table 1.4
          Interface Specifications.
Burst mode sampling (example)
(a) Configure the sampling parameters.
  // Displacement RAW, temperature format 1, sampling counter value, checksum (output of all available data)
  Tx = \{0xFE, 0x01, 0x0d\}.
                                         /* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */
  Tx = \{0x80, 0x42, 0x0d\}.
                                         /* Write to SIG CTRL (L) to set output physical quantity = displacement,
                                           temperature format 1 */
  // See Section 7.1.3 for details on the procedure for setting the output physical quantities.
  Tx = \{0x88, 0x00, 0x0d\}.
                                         /* Write to UART_CTRL (L) to set UART Mode = manual sampling*/
                                         /* Write to BURST_CTRL (L) to set Burst counter = on, checksum = on */
  Tx = \{0x8C, 0x03, 0x0d\}.
  Tx = \{0x8D, 0xC7, 0x0d\}.
                                         /* Write to BURST_CTRL (H) to set Burst flag = on, temp = on, sensor = on */
  Tx = \{0xC6, 0x52, 0x0d\}.
                                         /* Write to X_ALARM (L) to set X detection threshold = 5 mm */
                                         /* Write to X_ALARM (H) */
  Tx = \{0xC7, 0x00, 0x0d\}.
                                         /* Write to Y_ALARM (L) to set Y detection threshold = 5 mm */
  Tx = \{0xC8, 0x52, 0x0d\}.
                                         /* Write to Y ALARM (H) */
  Tx = \{0xC9, 0x00, 0x0d\}.
  Tx = \{0xCA, 0x52, 0x0d\}.
                                         /* Write to Z_ALARM (L) to set Z detection threshold = 5 mm */
  Tx = \{0xCB, 0x00, 0x0d\}.
                                         /* Write to Z_ALARM (H) */
  Tx = \{0xFE, 0x00, 0x0d\}.
                                         /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
(b) Start sampling.
  Tx = \{0x83, 0x01, 0x0d\}.
                                         /* Write to MODE_CTRL (H) to go to Sampling mode */
  // Note) For the transition duration from Configuration mode to Sampling mode, refer to "Sampling Start Time" in Table 1.4
          Interface Specifications.
  // Note) For the transient response time (output hold time) of FIR filters, refer to Table 4.2 Transient response time of FIR
          filters at the start of measurement.
(c) A burst command is sent when Data Ready signal is asserted.
  Tx = \{0x80, 0x00, 0x0d\}.
                                         /* Write to BURST (L) */
(d) Retrieve sampling data.
  Rx = \{0x80,
      FLAG_H, FLGA_L,
      TEMP1_H, TEMP1_L
      XVCCL_HIGH_L, XVCCL_LOW_H, XVCCL_LOW_L,
      YVCCL_HIGH_L, YVCCL_LOW_H, YVCCL_LOW_L,
```

ZVCCL_HIGH_L, ZVCCL_LOW_H, ZVCCL_LOW_L,

```
COUNT H, COUNT L
      CHECKSUM_H, CHECKSUM_L,
      0x0d}
  // Repeat (c) and (d).
(e) Stop sampling.
  Tx = \{0x83, 0x02, 0x0d\}.
                                          /* Write to MODE_CTRL (H) to go to Configuration mode */
  // Note) For the transition duration from Sampling mode to Configuration mode, refer to "Sampling Stop Time" in Table 1.4
          Interface Specifications.
7.1.5. Self Test (UART)
Structural Resonance Level Test
(a) Perform a structural resonance level test.
  Tx = \{0xFE, 0x01, 0x0d\}.
                                          /* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */
                                          /* Write to MSC_CTRL (H) to set EXI_TEST = 1 */
  Tx = \{0x83, 0x80, 0x0d\}.
(b) Wait until the test is completed.
  // Wait for the time specified in "Self Test Time (Structural Resonance Level Test)"
  // Or verify EXI_TEST of register: MSC_CTRL [0x02(W1)], bit [15] returns to 0 as shown below.
                                          /* Read out MSC_CTRL */
  Tx = \{0x02, 0x00, 0x0d\}.
                                          /* Retrieve the response value */
  Rx = \{0x02, MSByte, LSByte, 0x0d\}.
  // if EXI_TEST is 0, the test is complete; if 1, repeat (b) since the test in progress.
(c) Confirm the test results.
  // Check X EXI LEVEL, Y EXI LEVEL, Z EXI LEVEL in register: DIAG STAT2 [0x0C(W0)], bit [13-8].
  Tx = \{0xFE, 0x00, 0x0d\}.
                                          /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
  Tx = \{0x0C, 0x00, 0x0d\}.
                                          /* Read out DIAG_STAT2 */
  Rx = {0x0C, MSByte, LSByte, 0x0d}. /* Retrieve the response value */
// if X_EXI_LEVEL, Y_EXI_LEVEL, Z_EXI_LEVEL are "00", the diagnosis result is OK; if any value is "01", the diagnosis
   result for the corresponding axis is NG.
  // Note) This structural resonance level test cannot be run with other tests at the same time.
Data Consistency Test in Nonvolatile Memory (Flash Test)
(a) Perform a Flash test.
  Tx = \{0xFE, 0x01, 0x0d\}.
                                          /* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */
  Tx = \{0x83, 0x08, 0x0d\}.
                                          /* Write to MSC_CTRL (H) to set FLASH_TEST = 1 */
(b) Wait until the test is completed.
  // Wait for the time specified in "Self Test Time (Flash Test)".
  // Or verify FLASH_TEST of register: MSC_CTRL [0x02(W1)], bit [11] returns to 0 as shown below.
                                          /* Read out MSC CTRL */
  Tx = \{0x02, 0x00, 0x0d\}.
                                          /* Retrieve the response value */
  Rx = \{0x02, MSByte, LSByte, 0x0d\}.
  // if FLASH_TEST is 0, the test is complete; if 1, repeat (b) since the tests in progress.
(c) Confirm the test results
  // Check FLASH_ERR in register: DIAG_STAT1 [0x04(W0)], bit [2]
  Tx = \{0xFE, 0x00, 0x0d\}.
                                          /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
                                          /* Read out DIAG STAT1 */
  Tx = \{0x04, 0x00, 0x0d\}.
                                         /* Retrieve the response value */
  Rx = \{0x04, MSByte, LSByte, 0x0d\}.
  // if FLASH_ERR is 0, the diagnosis result is OK; if 1, the diagnosis result is NG.
  // Note) This Flash test cannot be run with other tests at the same time.
Acceleration value test, Temperature value test, Power supply voltage level test
(a) Acceleration value test, Temperature value test, Power supply voltage level test are performed simultaneously.
  Tx = \{0xFE, 0x01, 0x0d\}.
                                          /* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */
  Tx = \{0x83, 0x07, 0x0d\}.
                                          /* Write to MSC_CTRL (H) to set ACC_TEST/TEMP_TEST/VDD_TEST = 1 */
(b) Wait until the tests are completed.
  // Wait for the time specified in "Self Test Time (ACC Test, TEMP Test, VDD Test)".
  // Or verify ACC_TEST/TEMP_TEST/VDD_TEST of regster: MSC_CTRL [0x02(W1)], bit [10:8] return to 0 as shown below.
  Tx = \{0x02, 0x00, 0x0d\}.
                                          /* Read out MSC_CTRL */
  Rx = \{0x02, MSByte, LSByte, 0x0d\}.
                                          /* Retrieve the response value */
  // if any of ACC_TEST/TEMP_TEST/VDD_TEST is 0, the tests are complete; if any of them is 1, repeat (b) since the
   corresponding test is in progress.
(c) Confirm the test results
  // Check TEMP_ERR/VDD_ERR/ACC_ERR_ALL in register: DIAG_STAT1 [0x04(W0)], bit [9,8,1].
  Tx = {0xFE, 0x00, 0x0d}.
                                          /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
                                          /* Read out DIAG_STAT1 */
  Tx = \{0x04, 0x00, 0x0d\}.
                                          /* Retrieve the response value */
  Rx = \{0x04, MSByte, LSByte, 0x0d\}.
```

result for the corresponding test is NG.

// if any of TEMP ERR/VDD ERR/ACC ERR ALL is 0, the diagnosis results are OK; if any of them is 1, the diagnosis

// The acceleration bias value obtained by the acceleration test can be retrieved from ACC_SELFTEST_DATA1 and ACC_SELFTEST_DATA2 registers.

```
7.1.6. Software Reset (UART)
```

```
(a) Execute a software reset.

Tx = {0xFE, 0x01, 0x0d}.

Tx = {0x8A, 0x80, 0x0d}.

/* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */

Tx = {0x8A, 0x80, 0x0d}.

/* Write to GLOB_CMD (L) to set SOFT_RST = 1 */

(b) Wait until the software reset is finished.

// Wait for the time specified in "Reset Recovery Time".
```

7.1.7. Non-Volatile Memory Backup (UART)

```
(a) Backup the current register setting values to non-volatile memory.
                                         /* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */
  Tx = \{0xFE, 0x01, 0x0d\}.
                                         /* Write to GLOB_CMD (L) to set FLASH_BACKUP = 1 */
  Tx = \{0x8A, 0x08, 0x0d\}.
(b) Wait until the backup is completed.
  // Wait for the time specified in "Flash Backup Time".
  // Or verify FLASH_BACKUP of register: GLOB_CMD[0x0A(W1)], bit [3] returns to 0 as shown below.
  Tx = \{0x0A, 0x00, 0x0d\}.
                                         /* Read out GLOB_CMD */
  Rx = \{0x0A, MSByte, LSByte, 0x0d\}.
                                        /* Retrieve the response value */
  // if FLASH_BACKUP is 0, the backup is complete; if 1, repeat (b) since the backup is in progress.
(c) Confirm the backup result.
  // Check FLASH_BU_ERR in register: DIAG_STAT1 [0x04(W0)], bit [0].
  Tx = \{0xFE, 0x00, 0x0d\}.
                                         /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
  Tx = \{0x04, 0x00, 0x0d\}.
                                         /* Read out DIAG_STAT1 */
                                         /* Retrieve the response value */
  Rx = \{0x04, MSByte, LSByte, 0x0d\}.
  // if FLASH_BU_ERR is 0, the backup completes successfully; if 1, an error occurred.
```

7.1.8. Non-Volatile Memory Reset (UART)

```
(a) Restores the register setting values in non-volatile memory to the factory defaults.
  Tx = \{0xFE, 0x01, 0x0d\}.
                                          /* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */
                                          /* Write to GLOB_CMD (L) to set FLASH_RST = 1 */
  Tx = \{0x8A, 0x04, 0x0d\}.
(b) Wait until the memory reset is completed.
  // Wait for the time specified in "Flash Reset Time".
  // Or verify FLASH_RST of register: GLOB_CMD [0x0A(W1)], bit [2] returns to 0 as shown below.
  Tx = \{0x0A, 0x00, 0x0d\}.
                                          /* Read out GLOB_CMD */
  Rx = \{0x0A, MSByte, LSByte, 0x0d\}.
                                         /* Retrieve the response value */
  // if FLASH_RST is 0, the reset is complete; if 1, repeat (b) since the reset is in progress.
(c) Confirm the reset result.
  // Check FLASH_BU_ERR in register: DIAG_STAT1 [0x04(W0)], bit [0].
                                          /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
  Tx = \{0xFE, 0x00, 0x0d\}.
  Tx = \{0x04, 0x00, 0x0d\}.
                                          /* Read out DIAG_STAT1 */
                                         /* Retrieve the response value */
  Rx = \{0x04, MSByte, LSByte, 0x0d\}.
  // if FLASH_BU_ERR is 0, the reset is finished successfully; if 1, an error occurred.
(d) Reboot or reset the device.
```

7.1.9. Sleep Sequence (UART)

```
(a) Go to sleep mode.

Tx = {0xFE, 0x00, 0x0d}. /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */
Tx = {0x83, 0x03, 0x0d}. /* Write to MODE_CTRL (H) to go to sleep mode */
(b) Wake up from sleep mode by detecting an edge trigger on the EXT pin.

// Input an edge trigger on the EXT pin.

// Note) UART communication is not available in sleep mode.
(c) Wait until the transition to the configuration mode is complete.

// Wait for the time specified in "Sleep Wake-up Time".
```

7.1.10. Auto Start (UART only)

```
(a) Enable an Auto start function.

Tx = {0xFE, 0x01, 0x0d}.

Tx = {0x88, 0x03, 0x0d}.

/* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */

Tx = {0x88, 0x03, 0x0d}.

/* Write to UART_CTRL (L) to satisfy AUTO_START • UART_AUTO = 1 */

(b) Execute a non-volatile memory backup, see Chapter 7.1.7.

(c) Reboot or reset the device.

(d) Wait for the time specified in "Power-On Start-Up Time / Reset Recovery Time".
```

(e) Transmission of sampling data will start automatically.

7.1.11. UART Communication Baud Rate Setting (UART only)

```
(a) Change the UART communication baud rate from 460.8 kbps (factory default setting) to 921.6 kbps.

Tx = {0xFE, 0x01, 0x0d}. /* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */

Tx = {0x89, 0x00, 0x0d}. /* Write to UART_CTRL (H) to set BAUD_RATE = "00" */

// Note) The configured baud rate is effective immediately after writing.
```

- (b) Change the communication baud rate of the host to 921.6 kbps, and restart UART communication.
- (c) To keep the communication baud rate of the device after reboot, perform a non-volatile memory backup, see chapter 7.1.7.

7.2. SPI Sample Programs

To use SPI interface, disable a UART Auto mode. Other operating procedures are the same as those for UART. The basic operation examples are shown below.

7.2.1. Disable UART Auto Mode (SPI)

```
(a) Disable a UART Auto mode.

Tx = {0xFE01} / Rx = {0x----}.

Tx = {0x8800} / Rx = {0x----}.

/* Write to WIN_CTRL (L) to set WINDOW_ID = 1 */

/* Write to UART_CTRL (L) to satisfy AUTO_START • UART_AUTO = 0 */

// -: don't care
```

7.2.2. Register Read and Write (SPI)

Register Read Example

```
(a) Read 16-bit data from the register (Address = 0x02 / Window = 0). 
 Tx = \{0xFE00\} / Rx = \{0x---\}. /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */ Tx = \{0x0200\} / Rx = \{0x---\}. /* Read out MODE_CTRL */ Tx = \{0x---\} / Rx = \{0x0400\}. /* Retrieve the response value */ // -: don't care // High byte of Rx data "0x04" indicates a configuration mode. // Low byte of Rx data "0x04" indicates Reserved. // Read data is by 16 bits with MSB first format.
```

Register Write Example

```
(a) Write 8-bit data to the register (Address=0x03 / Window =0).

Tx = \{0xFE00\} / Rx = \{0x----\}. /* Write to WIN_CTRL (L) to set WINDOW_ID = 0 */ Tx = \{0x8301\} / Rx = \{0x----\}. /* Write to MODE_CTRL (H) to go to sampling mode. */ // -: don't care // No corresponding response for data writing. // Write data is by 8 bits
```

8. Handling Notes

8.1. Cautions for Use

- When you attach the product to a housing, equipment, jig, or tool, make sure you attach it properly so that no mechanical
 stress is added to create a distortion such as a warp or twist. In addition, tighten the screws firmly but not too firmly because
 the mount of the product may break. Use screw locking techniques as necessary.
- When you set up the product, make sure the equipment, jigs, tools, and workers maintain a good ground in order not to generate high voltage leakage. If you add overcurrent or static electricity to the product, the product may be damaged permanently.
- When you install the product, make sure metallic or other conductors do not enter the product. Otherwise, malfunction or damage of the product may result.
- If excessive shock is added to the product when, for example, the product falls, the quality of the product may be degraded.

 Make sure the product does not fall when you handle it.
- Before you start using the product, test it in the actual equipment under the actual operating environment.
- Since the product has capacitors inside, inrush current will occur during power-on. Evaluate in the actual environment in order to check the effect of the supply voltage drop by inrush current in the system.
- If water enters the product, malfunction or damage of the product may result. If the product can be exposed to water, the system must have a waterproof structure. We do not guarantee the operation of the product when the product is exposed to condensation, dust, oil, corrosive gas (salt, acid, alkaline, or the like), or direct sunlight.
- This product is not designed to be radiation resistant.
- Never use this product if the operating condition is over the absolute maximum rating. If you do, the characteristics of the
 product may never recover.
- If the product is exposed to excessive exogenous noise or the like, degradation of the precision, malfunction, or damage
 of the product may result. The system needs to be designed so that the noise itself is suppressed or the system is immune
 to the noise.
- Mechanical vibration or shock, continuous mechanical stress, rapid temperature change, or the like may cause cracks or disconnections at the various connecting parts.
- Take sufficient safety measure for the equipment this product is built into.
- This product is not intended for general use by the consumer but instead for engineering design. For the customer, please consider it safely with the proper use.
- This product is not designed to be used in the equipment that demands extremely high reliability and where its failure may
 threaten human life or property (for example, aerospace equipment, submarine repeater, nuclear power control equipment,
 life support equipment, medical equipment, transportation control equipment, etc.). Therefore, Seiko Epson Corporation
 will not be liable for any damages caused by the use of the product for those applications.
- Do not alter or disassemble the product.

8.2. Cautions for Storage

- Do not add shock or vibration to the packing box. Do not spill water over the packing box. Do not store or use the product in the environment where dew condensation occurs due to rapid temperature change.
- To suppress the characteristic change by prolonged storage, it is recommended to maintain the environment at normal temperature and normal humidity. Normal temperature: +5 ~ +35 °C Normal humidity: 45 %RH ~ 85 %DH (JIS Z 8703).
- Do not store the product in a location subject to High Temperature, high humidity, under direct sunlight, corrosive gas or dust.
- Do not put mechanical stress on the product while it is stored.

8.3. Other Cautions

- When you connect the socket to the header of this product, make sure you do not insert the header in the reverse orientation. If you do, the product may be damaged permanently.
- The gloss marks derived from the adhesive material may have appeared on the casing surface of the product, but it does
 not affect the function and quality of the product.
- The Parting line as a result of manufacturing process may have appeared on the casing surface of the product, but it is not an abnormality.
- Please take care not to tamper with or accidently disturb the assembly screw when attaching and detaching the product to
 the system. We do not guarantee the performance and the quality of the product in case the assembly screw is manipulated.
- The product contains quartz crystal oscillator created by microfabrication. Take precaution to prevent falling or excessive impact. Do not use the product after an accidental fall or it experiences excessive impact. The possibility of a failure and

risk of malfunction from failure increases.

- If environmental vibration is expected in the resonance frequency band of this product, take sufficient countermeasures before use.
- If a radio (transmission antenna) is set up near this product, degradation of the precision may result by radio frequency interference. Place the radio (transmission antenna) as far away as possible or add shielding to mitigate the effects of radio frequency interference.
- · Never turn off power while the host communicates the product. Otherwise, malfunction of the product may result.
- Small performance deterioration due to long-term use and aging effects, etc. cannot be detected through the self-diagnosis test in this product. Discontinue use immediately even when the self-diagnosis test results in a "pass" when experiencing abnormality in the sensor performance.
- Exercise care and precaution with the packaging and during transport of the equipment that this product is installed on to avoid excessive vibration and or damage from impact.
- In general, when a vibration sensor is mounted on a target machine, resonance is generated due to contact. In particular, if there is a rattle in the mounting, the resonance caused by the contact will deteriorate the measurement accuracy. To prevent this, it is recommended to screw the product firmly to the machine to be measured.

8.4. Limited Warranty

The product warranty period is one year from the date of shipment.
 If a defect due to a quality failure of the product is found during the warranty period, we will promptly provide a replacement.

9. Contact

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Product Information on www server

https://global.epson.com/products_and_drivers/sensing_system/